

No. EA-179-180419

SELECTION GUIDE

The output voltage, the UVLO circuit, the auto-discharge function⁽¹⁾, the package, and the taping type for the device are user-selectable options.

Selection Guide

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
RP105Kxx1*-TR	DFN(PLP)1212-6	5,000 pcs	Yes	Yes
RP105Qxx2*-TR-FE ⁽²⁾	SC-88A	3,000 pcs	Yes	Yes
RP105Nxx1*-TR-FE	SOT-23-5	3,000 pcs	Yes	Yes
RP105Lxx1*-TR	DFN1212-5	5,000 pcs	Yes	Yes

xx: The set output voltage (V_{SET}) can be designated within the range of 0.6 V (06) to 1.5 V (15) in 0.1 V step.

If the set output voltage (V_{SET}) is designated in 0.01 V step, indicate the product name as follows.

1.05 V: RP105x10x*5-TR

*: CE pin polarity and auto-discharge function of the product can be defined as follows.

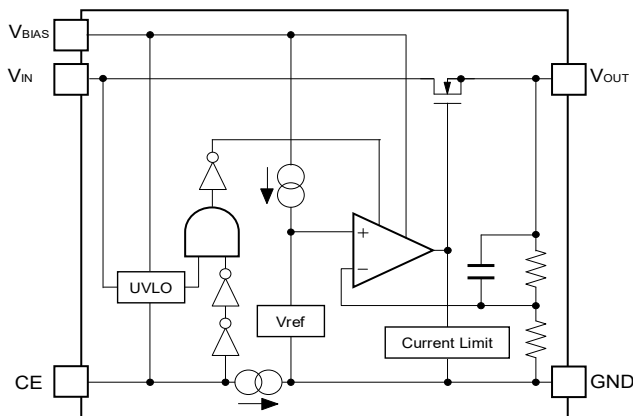
(B) "H" active, auto-discharge function is not included, UVLO is included

(D) "H" active, auto-discharge function is included, UVLO is included

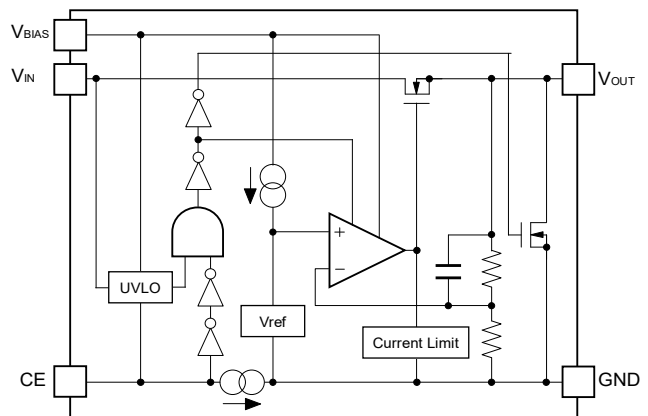
(E) "H" active, auto-discharge function is not included, UVLO is not included

(F) "H" active, auto-discharge function is included, UVLO is not included

BLOCK DIAGRAMS



RP105xxxxB/E Block Diagram

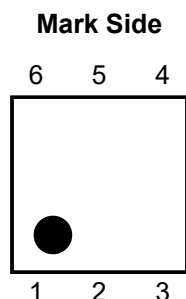


RP105xxxxD/F Block Diagram

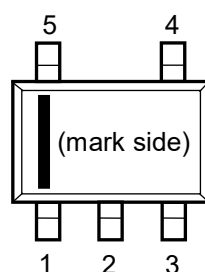
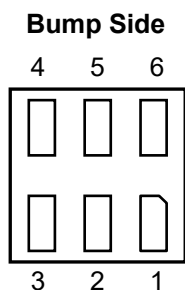
⁽¹⁾ Auto-discharge function quickly lowers the output voltage to 0 V, when the chip enable signal is switched from the active mode to the standby mode, by releasing the electrical charge accumulated in the external capacitor.

⁽²⁾ RP105Qxx2*-TR-FE supports only RP105Qxx2B/D.

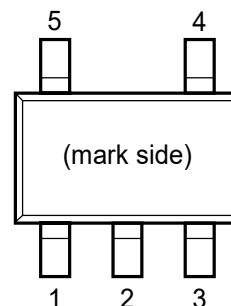
PIN DESCRIPTIONS



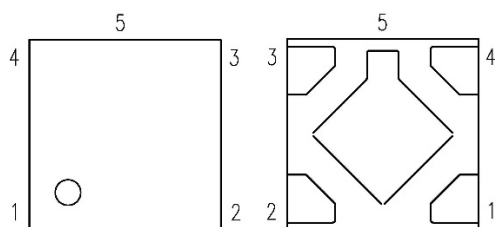
DFN(PLP)1212-6 Pin Configuration



**SC-88A
Pin Configuration**



**SOT-23-5
Pin Configuration**



DFN1212-5 Pin Configuration

DFN(PLP)1212-6 Pin Description

Pin No	Symbol	Pin Description
1	V_{BIAS}	Input Pin 1
2	GND	Ground Pin
3	CE	Chip Enable Pin ("H" Active)
4	V_{IN}	Input Pin 2
5	NC	No Connection
6	V_{OUT}	Output Pin

SC-88A Pin Description

Pin No	Symbol	Pin Description
1	V_{BIAS}	Input Pin 1
2	GND	Ground Pin
3	V_{OUT}	Output Pin
4	V_{IN}	Input Pin 2
5	CE	Chip Enable Pin ("H" Active)

*RP105Q (SC-88A) is the discontinued product as of April, 2018.

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SOT-23-5 Pin Description

Pin No	Symbol	Pin Description
1	V_{IN}	Input Pin 2
2	GND	Ground Pin
3	CE	Chip Enable Pin ("H" Active)
4	V_{BIAS}	Input Pin 1
5	V_{OUT}	Output Pin

DFN1212-5 Pin Description

Pin No	Symbol	Pin Description
1	V_{OUT}	Output Pin
2	V_{BIAS}	Input Pin 1
3	CE	Chip Enable Pin ("H" Active)
4	V_{IN}	Input Pin 2
5	GND	Ground Pin

ABSOLUTE MAXIMUM RATINGS

Absolute Maximum Ratings

Symbol	Item			Rating	Unit
V _{BIAS}	Input Voltage			6.0	V
V _{IN}	Input Voltage (for Driver)			−0.3 to V _{BIAS} + 0.3	V
V _{CE}	Input Voltage (CE Pin)			6.0	V
V _{OUT}	Output Voltage			−0.3 to V _{IN} + 0.3	V
I _{OUT}	Output Current			500	mA
P _D	Power Dissipation ⁽¹⁾	DFN(PLP)1212-6	JEDEC STD. 51-7 Test Land Pattern	450	mW
		SC-88A	Standard Test Land Pattern	380	
		SOT-23-5	JEDEC STD. 51-7 Test Land Pattern	660	
		DFN1212-5	JEDEC STD. 51-7 Test Land Pattern	560	
T _j	Junction Temperature Range			−40 to 125	°C
T _{stg}	Storage Temperature Range			−55 to 125	°C

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

RECOMMENDED OPERATING CONDITIONS

Recommended Operating Conditions

Recommended Operating Conditions			
Symbol	Item	Rating	Unit
V _{BIAS}	Input Voltage Range	2.4 to 5.25	V
V _{IN}		0.9 to V _{BIAS}	V
		V _{SET} + 0.1 to V _{BIAS} (RP105xxxxB/D and when V _{SET} ≥ 0.8 V)	V
T _a	Operating Temperature Range	−40 to 85	°C

RECOMMENDED OPERATING CONDITIONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

⁽¹⁾ Refer to *POWER DISSIPATION* for detailed information.

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ELECTRICAL CHARACTERISTICS

$V_{BIAS} = V_{CE} = 3.6 \text{ V}$, $V_{IN} = \text{Set } V_{OUT} + 0.5 \text{ V}$, $I_{OUT} = 1 \text{ mA}$, $C_{BIAS} = C_{IN} = 1.0 \mu\text{F}$, $C_{OUT} = 2.2 \mu\text{F}$, unless otherwise noted.

The specifications surrounded by are guaranteed by design engineering at $-40^\circ\text{C} \leq T_a \leq 85^\circ\text{C}$.

RP105x

($T_a = 25^\circ\text{C}$)

Symbol	Item	Conditions	Min.	Typ.	Max.	Unit
V_{OUT}	Output Voltage	$T_a = 25^\circ\text{C}$	Set V_{OUT} -15 mV		Set V_{OUT} + 15 mV	V
		$-40^\circ\text{C} \leq T_a \leq 85^\circ\text{C}$	Set V_{OUT} -20 mV		Set V_{OUT} + 20 mV	V
I_{OUT}	Output Current		400			mA
$\Delta V_{OUT} / \Delta I_{OUT}$	Load Regulation (K, Q, N package)	$1 \text{ mA} \leq I_{OUT} \leq 400 \text{ mA}$		30	50	mV
	Load Regulation (L package)	$1 \text{ mA} \leq I_{OUT} \leq 400 \text{ mA}$		15	35	mV
V_{DIF}	Dropout Voltage	Refer to <i>PRODUCT-SPECIFIC ELECTRICAL CHARACTERISTICS</i>				
I_{SS}	Supply Current	$I_{OUT} = 0 \text{ mA}$		28	40	μA
$I_{standby}$	Standby Current	$V_{CE} = 0 \text{ V}$		0.1	3.0	μA
$\Delta V_{OUT} / \Delta V_{IN}$	Line Regulation	$2.4 \text{ V} \leq V_{BIAS} \leq 5.0 \text{ V}$		0.02	0.1	%/V
		Set $V_{OUT} + 0.3 \text{ V} \leq V_{IN} \leq 2.4 \text{ V}$		0.02	0.1	
RR	Ripple Rejection	$I_{OUT} = 30 \text{ mA}$, $f = 1 \text{ kHz}$ V_{IN} Ripple 0.2 Vp-p		80		dB
		$I_{OUT} = 30 \text{ mA}$, $f = 1 \text{ kHz}$ V_{BIAS} Ripple 0.2 Vp-p		50		
V_{BIAS}	Input Voltage ⁽¹⁾	$V_{OUT} < 0.8 \text{ V}$	2.4		5.25	V
		$V_{OUT} \geq 0.8 \text{ V}$	Set V_{OUT} + 1.6		5.25	
V_{IN}	Input Voltage (for Driver) ⁽¹⁾	RP105xxxxB/D	$V_{OUT} < 0.8 \text{ V}$	0.9	V_{BIAS}	V
			$V_{OUT} \geq 0.8 \text{ V}$	Set V_{OUT} + 0.1	V_{BIAS}	
		RP105xxxxE/F	0.9		V_{BIAS}	
$\Delta V_{OUT} / \Delta T_a$	Output Voltage Temperature Coefficient	$-40^\circ\text{C} \leq T_a \leq 85^\circ\text{C}$		± 50		ppm / $^\circ\text{C}$
I_{SC}	Short Current Limit	$V_{OUT} = 0 \text{ V}$		120		mA
I_{CEPD}	CE Pull-down Current			1.0		μA

All test items listed under Electrical Characteristics are done under the pulse load condition ($T_j \approx T_a = 25^\circ\text{C}$) except Output Noise, Ripple Rejection and Output Voltage Temperature Coefficient.

⁽¹⁾ The maximum Input Voltage listed under Electrical Characteristics is 5.25 V. If for any reason the input voltage exceeds 5.25 V, it has to be no more than 5.5 V with 500 hours of the total operating time.

ELECTRICAL CHARACTERISTICS (continued)

$V_{BIAS} = V_{CE} = 3.6\text{ V}$, $V_{IN} = \text{Set } V_{OUT} + 0.5\text{ V}$, $I_{OUT} = 1\text{ mA}$, $C_{BIAS} = C_{IN} = 1.0\text{ }\mu\text{F}$, $C_{OUT} = 2.2\text{ }\mu\text{F}$, unless otherwise noted.

The specifications surrounded by are guaranteed by design engineering at $-40^{\circ}\text{C} \leq T_a \leq 85^{\circ}\text{C}$.

RP105x

($T_a = 25^{\circ}\text{C}$)

Symbol	Item	Conditions	Min.	Typ.	Max.	Unit
V_{CEH}	CE Input Voltage "H"		0.8			V
V_{CEL}	CE Input Voltage "L"				0.3	V
$V_{IN\text{ UVLO}}$	V_{IN} Under Voltage Lock Out (only RP105xxxxB/D)	$I_{OUT} = 1.0\text{ }\mu\text{A}$		Set $V_{OUT} + 50\text{ mV}$	Set $V_{OUT} + 100\text{ mV}$	V
t _{delay}	Detector Delay Time (only RP105xxxxB/D)			100		μs
en	Output Noise	BM = 10 Hz to 100 kHz $I_{OUT} = 30\text{ mA}$, Set $V_{OUT} = 0.6\text{ V}$		70		μV_{rms}
R_{LOW}	Nch On Resistance For auto-discharge (only RP105xxxxD/F)	$V_{BIAS} = 3.6\text{ V}$, $V_{CE} = \text{"L"}$		50		Ω

All test items listed under Electrical Characteristics are done under the pulse load condition ($T_j \approx T_a = 25^{\circ}\text{C}$) except Output Noise, Ripple Rejection and Output Voltage Temperature Coefficient.

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PRODUCT-SPECIFIC ELECTRICAL CHARACTERISTICS

DFN(PLP)1212-6, SC-88A, SOT-23-5















The specifications surrounded by are guaranteed by design engineering at $-40^{\circ}\text{C} \leq T_a \leq 85^{\circ}\text{C}$

Dropout Voltage


Set V_{OUT} (V)	V_{BIAS} (V)	V_{GS} (V)	V_{DIF} ($I_{\text{OUT}} = 300 \text{ mA}$) (V)		V_{DIF} ($I_{\text{OUT}} = 400 \text{ mA}$) (V)	
			Typ.	Max.	Typ.	Max.
0.6	3.6	3.0	0.115	0.180	0.180	0.320
0.7	3.6	2.9	0.120	0.190	0.180	0.320
0.8	3.6	2.8	0.120	0.190	0.180	0.300
0.9	3.6	2.7	0.120	0.190	0.180	0.300
1.0	3.6	2.6	0.120	0.190	0.180	0.280
1.1	3.6	2.5	0.120	0.190	0.180	0.280
1.2	3.6	2.4	0.130	0.200	0.180	0.280
1.3	3.6	2.3	0.130	0.200	0.180	0.260
1.4	3.6	2.2	0.130	0.200	0.180	0.260
1.5	3.6	2.1	0.130	0.200	0.180	0.260

Dropout Voltage (V_{GS} (V), V_{DIF} (V), $I_{\text{OUT}} = 200 \text{ mA}$)

($T_a = 25^{\circ}\text{C}$)

Set V_{OUT} (V)	$V_{\text{BIAS}} = 2.5 \text{ V}$		$V_{\text{BIAS}} = 3.0 \text{ V}$		$V_{\text{BIAS}} = 3.3 \text{ V}$		$V_{\text{BIAS}} = 3.6 \text{ V}$		$V_{\text{BIAS}} = 4.2 \text{ V}$		$V_{\text{BIAS}} = 5.0 \text{ V}$	
	V_{GS} (V)	V_{DIF} (V)	V_{GS} (V)	V_{DIF} (V)	V_{GS} (V)	V_{DIF} (V)	V_{GS} (V)	V_{DIF} (V)	V_{GS} (V)	V_{DIF} (V)	V_{GS} (V)	V_{DIF} (V)
0.6	1.9	-	2.4	-	2.7	-	3.0	-	3.6	-	4.4	-
0.7	1.8	-	2.3	-	2.6	-	2.9	-	3.5	-	4.3	-
0.8	1.7	0.098	2.2	0.093	2.5	0.093	2.8	0.092	3.4	0.092	4.2	0.092
0.9	1.6	0.098	2.1	0.094	2.4	0.093	2.7	0.092	3.3	0.092	4.1	0.092
1.0			2.0	0.094	2.3	0.093	2.6	0.092	3.2	0.092	4.0	0.092
1.1			1.9	0.096	2.2	0.094	2.5	0.094	3.1	0.093	3.9	0.093
1.2			1.8	0.098	2.1	0.096	2.4	0.095	3.0	0.095	3.8	0.094
1.3			1.7	0.098	2.0	0.096	2.3	0.095	2.9	0.095	3.7	0.095
1.4			1.6	0.098	1.9	0.096	2.2	0.095	2.8	0.095	3.6	0.095
1.5					1.8	0.096	2.1	0.095	2.7	0.095	3.5	0.095

All of units are tested and specified under load conditions such that $T_j \approx T_a = 25^{\circ}\text{C}$ except for Output Noise, Ripple Rejection and Output Voltage Temperature Coefficient items.

 V_{BIAS} pin voltage must be equal or more than Set $V_{\text{OUT}} + 1.6 \text{ V}$.

DFN1212-5



















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Dropout Voltage


Set V_{OUT} (V)	V_{BIAS} (V)	V_{GS} (V)	V_{DIF} ($I_{\text{OUT}} = 300 \text{ mA}$) (V)		V_{DIF} ($I_{\text{OUT}} = 400 \text{ mA}$) (V)	
			Typ.	Max.	Typ.	Max.
0.6	3.6	3.0	-	-	-	-
0.7	3.6	2.9	-	-	-	-
0.8	3.6	2.8	0.077	0.130	0.105	0.170
0.9	3.6	2.7	0.077	0.130	0.105	0.170
0.95	3.6	2.65	0.077	0.130	0.105	0.170
1.0	3.6	2.6	0.077	0.130	0.105	0.170
1.05	3.6	2.55	0.077	0.130	0.105	0.170
1.1	3.6	2.5	0.077	0.130	0.105	0.170
1.2	3.6	2.4	0.077	0.130	0.105	0.170
1.3	3.6	2.3	0.077	0.130	0.105	0.170
1.4	3.6	2.2	0.077	0.130	0.105	0.170
1.5	3.6	2.1	0.077	0.130	0.105	0.170

Dropout Voltage (V_{GS} (V), V_{DIF} (V), $I_{\text{OUT}} = 200 \text{ mA}$)

($T_a = 25^{\circ}\text{C}$)

Set V_{OUT} (V)	$V_{\text{BIAS}} = 2.5 \text{ V}$		$V_{\text{BIAS}} = 3.0 \text{ V}$		$V_{\text{BIAS}} = 3.3 \text{ V}$		$V_{\text{BIAS}} = 3.6 \text{ V}$		$V_{\text{BIAS}} = 4.2 \text{ V}$		$V_{\text{BIAS}} = 5.0 \text{ V}$	
	V_{GS} (V)	V_{DIF} (V)	V_{GS} (V)	V_{DIF} (V)	V_{GS} (V)	V_{DIF} (V)	V_{GS} (V)	V_{DIF} (V)	V_{GS} (V)	V_{DIF} (V)	V_{GS} (V)	V_{DIF} (V)
0.6	1.9	-	2.4	-	2.7	-	3.0	-	3.6	-	4.4	-
0.7	1.8	-	2.3	-	2.6	-	2.9	-	3.5	-	4.3	-
0.8	1.7	-	2.2	-	2.5	-	2.8	-	3.4	-	4.2	-
0.9	1.6	0.059	2.1	0.054	2.4	0.053	2.7	0.051	3.3	0.050	4.1	0.048
0.95			2.05	0.054	2.35	0.053	2.65	0.051	3.25	0.050	4.05	0.048
1.0			2.0	0.054	2.3	0.053	2.6	0.051	3.2	0.050	4.0	0.048
1.05			1.95	0.054	2.25	0.053	2.55	0.051	3.15	0.050	3.95	0.048
1.1			1.9	0.054	2.2	0.053	2.5	0.051	3.1	0.050	3.9	0.048
1.2			1.8	0.054	2.1	0.053	2.4	0.051	3.0	0.050	3.8	0.048
1.3			1.7	0.054	2.0	0.053	2.3	0.051	2.9	0.050	3.7	0.048
1.4			1.6	0.054	1.9	0.053	2.2	0.051	2.8	0.050	3.6	0.048
1.5					1.8	0.053	2.1	0.051	2.7	0.050	3.5	0.048

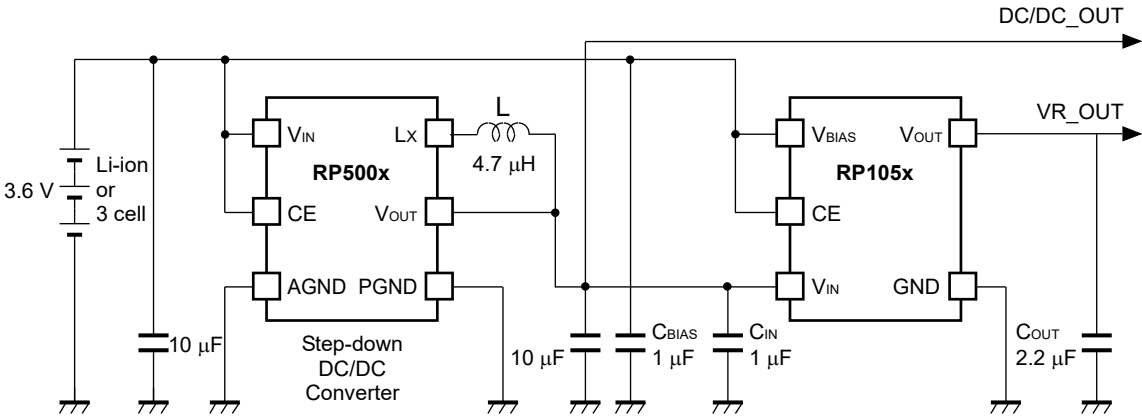
All of units are tested and specified under load conditions such that $T_j \approx T_a = 25^{\circ}\text{C}$ except for Output Noise, Ripple Rejection and Output Voltage Temperature Coefficient items.

 V_{BIAS} pin voltage must be equal or more than Set $V_{\text{OUT}} + 1.6 \text{ V}$.

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APPLICATION INFORMATION

TYPICAL APPLICATION



External Components

Symbol	Descriptions
C _{OUT}	2.2 µF, Ceramic Capacitor, GRM155B30J225ME15, MURATA
C _{BIAS} , C _{IN}	1.0 µF, Ceramic Capacitor, GRM155B31A105KE15, MURATA

TECHNICAL NOTES

UVLO (Undervoltage Lockout)

In RP105xxxxB/D, UVLO detects and turns off the output when the input voltage V_{IN} drops lower than or equal to $V_{SET} + 50 \text{ mV}$ (Typ.) while $CE = "H"$. Since RP105xxxxE/F does not have UVLO, it continues to output even if V_{IN} drops to $V_{SET} + 50 \text{ mV}$ (Typ.) or lower.

When V_{IN} drops below the set output voltage V_{SET} , UVLO does not turn off the output in RP105xxxxE/F while $CE = "H"$, therefore the current flows from V_{BIAS} pin to V_{IN} pin via the inside IC. This will not be generated in RP105xxxxB/D since UVLO turns off the output when V_{IN} is lower than or equal to $V_{SET} + 50 \text{ mV}$ (Typ).

Phase Compensation

In this device, phase compensation is made for securing stable operation even if the load current is varied. For this purpose, use a capacitor for C_{OUT} with the capacity of equal or more than $2.2 \mu\text{F}$.

If tantalum capacitors are connected as C_{OUT} , and if the equivalent series resistance (ESR) value is large, the operation might be unstable. Because of this, test the device with as same external components as ones to be used on the PCB.

PCB Layout

Make V_{BIAS} , V_{IN} , and GND lines sufficient. If their impedance is high, noise pickup or unstable operation may result. Connect a capacitor with a capacitance value as much as $1.0 \mu\text{F}$ or more between V_{BIAS} pin and GND, between V_{IN} pin and GND, and as close as possible to the pins.

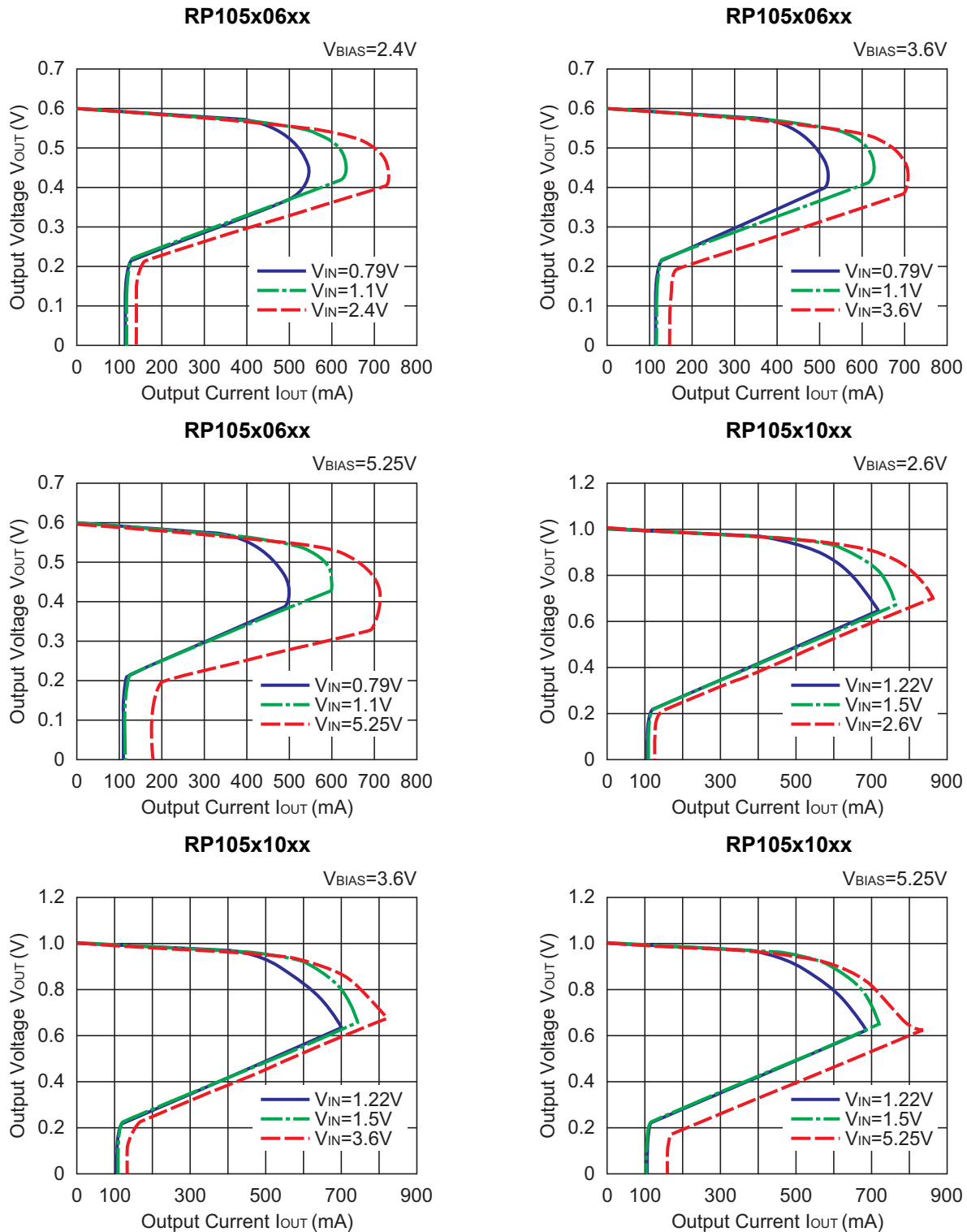
Set external components, especially the output capacitor, as close as possible to the device, and make wiring as short as possible. V_{IN} source is supposed to be the output of the DC/DC converter. The value should be equal or lower than V_{BIAS} voltage.

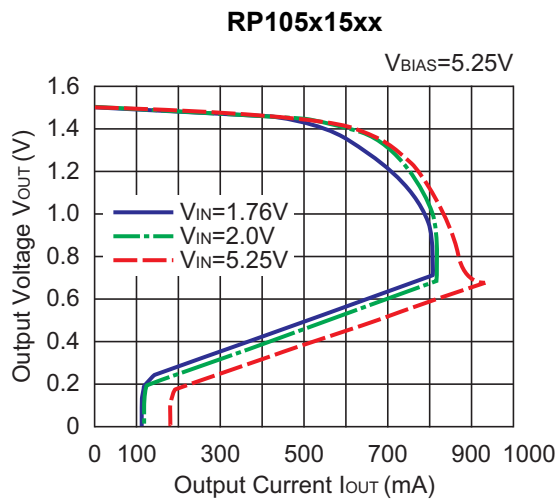
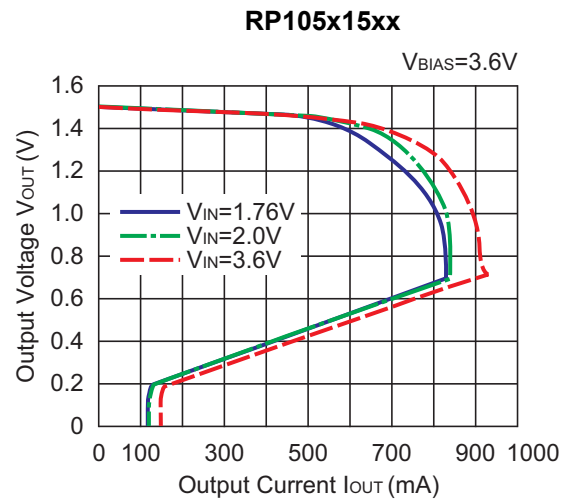
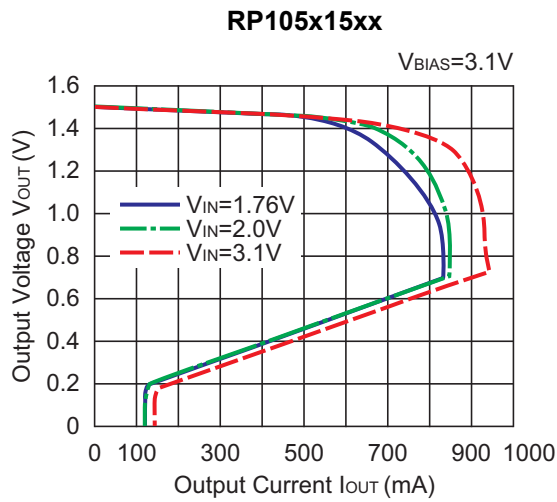
No. EA-179-180419

TYPICAL CHARACTERISTICS

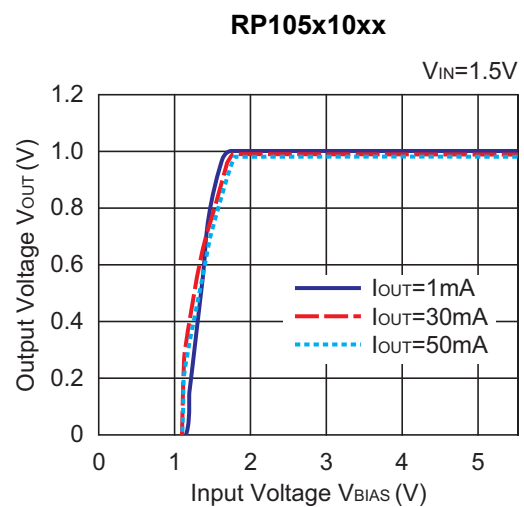
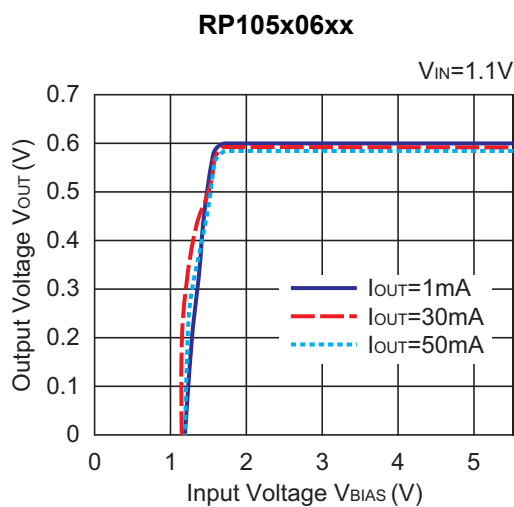
Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.

1) Output Voltage vs. Output Current ($C_{BIAS} = 1.0 \mu F$, $C_{IN} = C_{OUT} = 2.2 \mu F$, $T_a = 25^\circ C$)



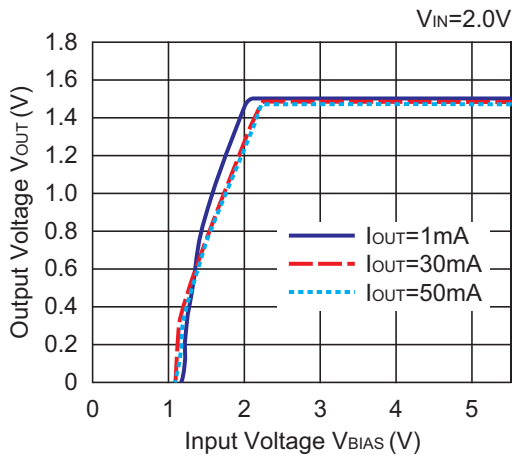


2) Output Voltage vs. Input Voltage ($C_{BIAS} = 1.0 \mu F$, $C_{IN} = C_{OUT} = 2.2 \mu F$, $T_a = 25^\circ C$)

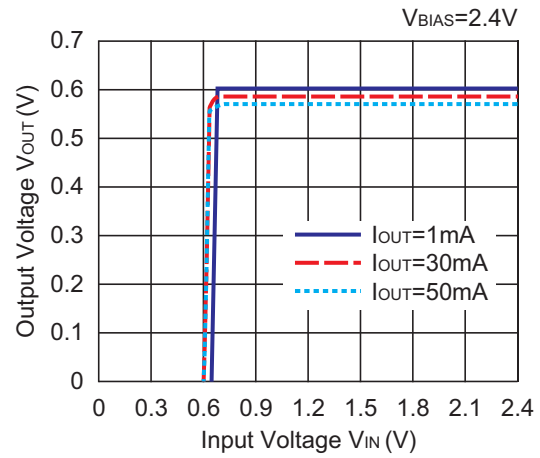


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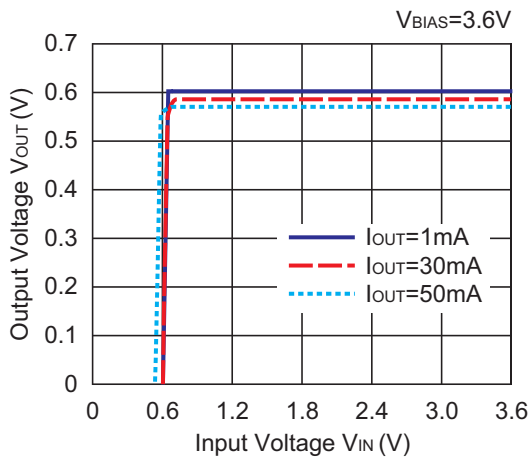
RP105x15xx



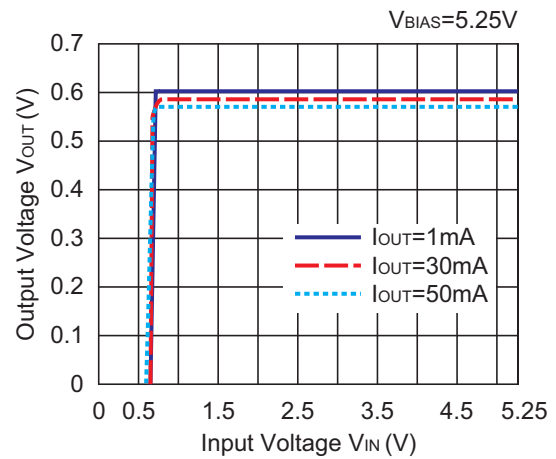
RP105x06xB/D



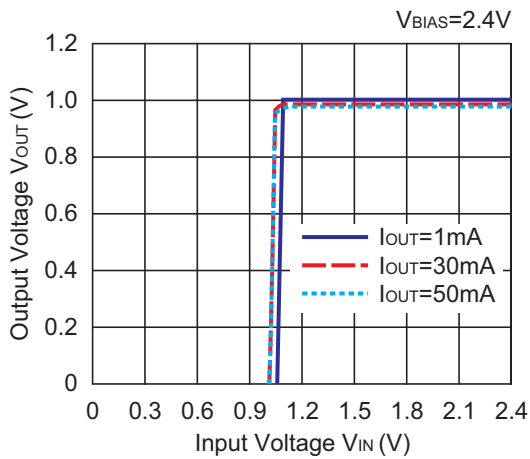
RP105x06xB/D



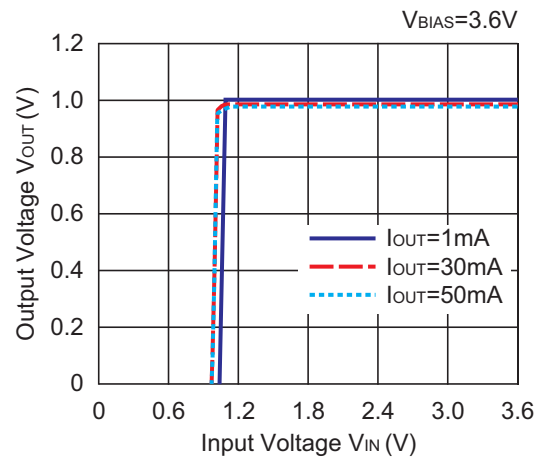
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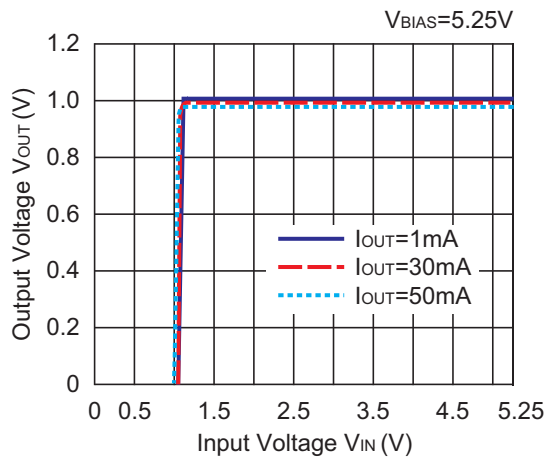
RP105x10xB/D



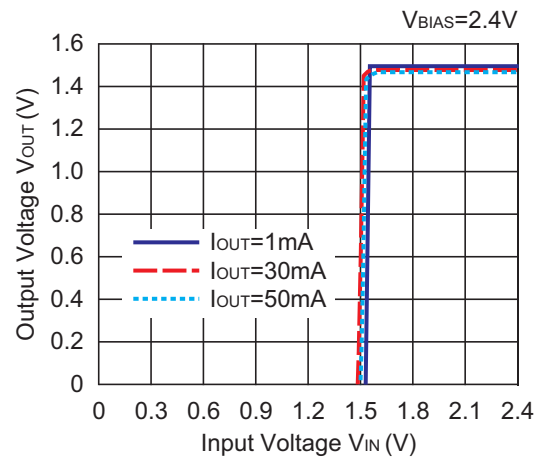
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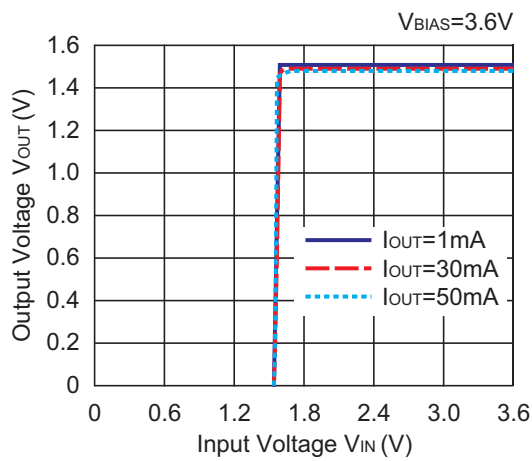
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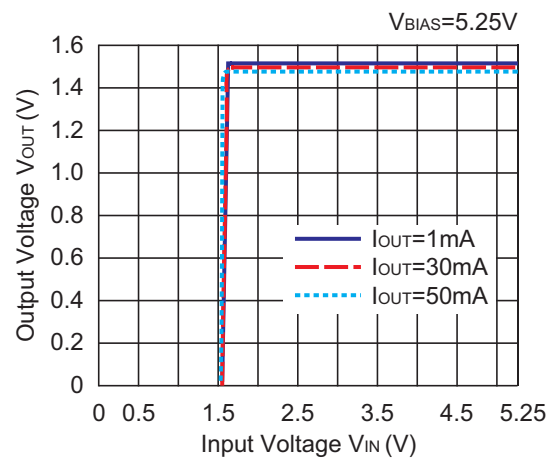
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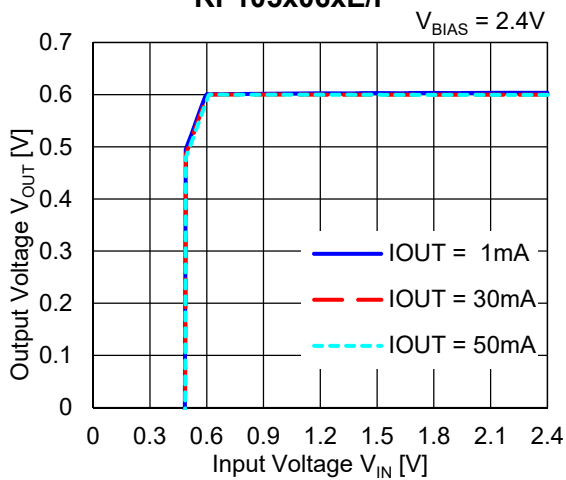
RP105x15xB/D



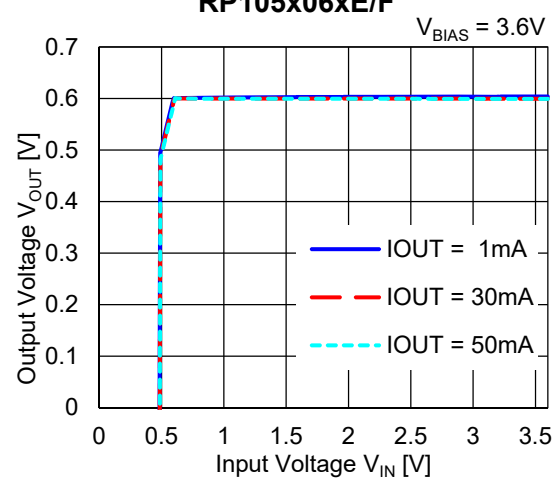
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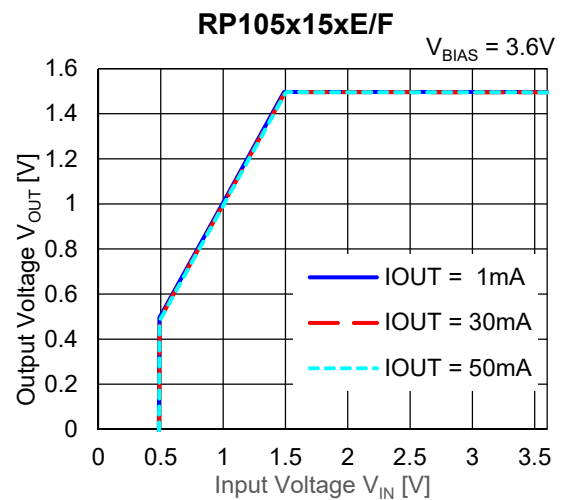
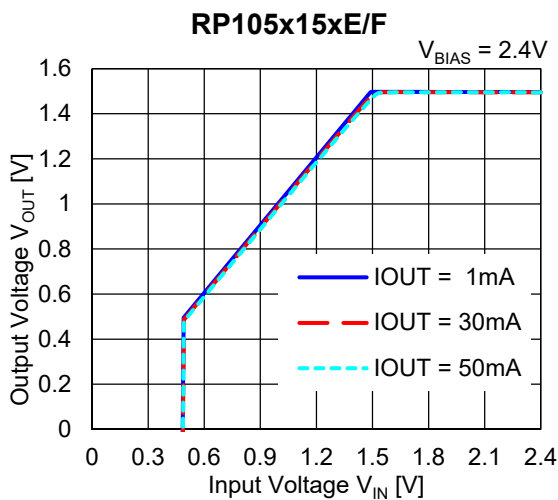
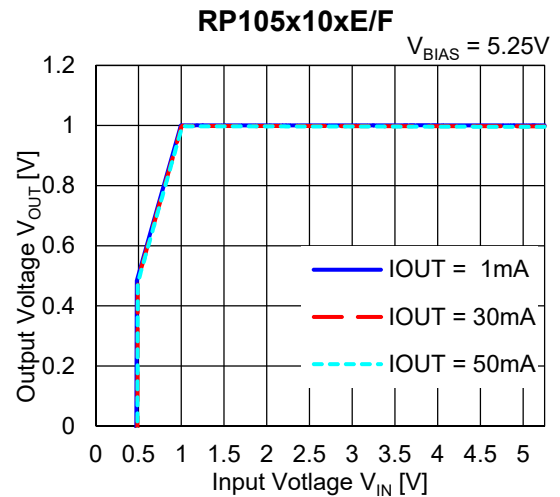
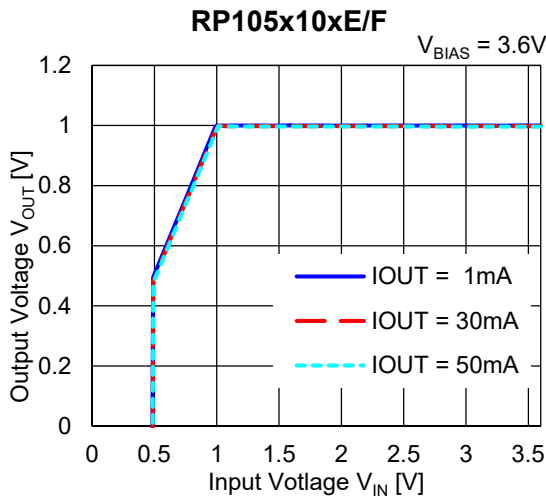
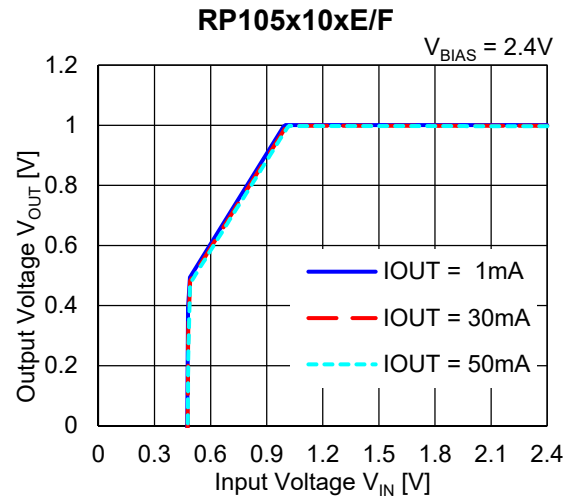
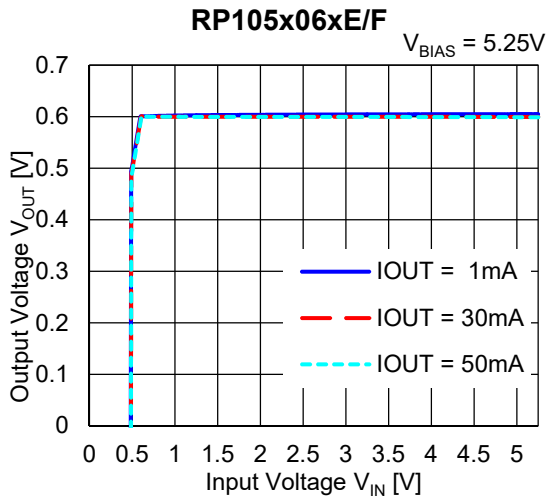
RP105x06xE/F

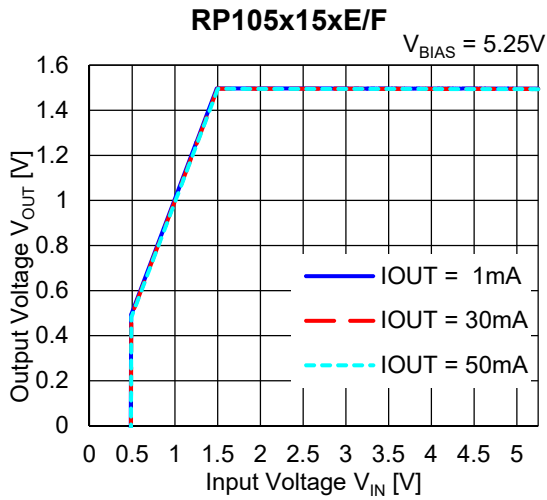


RP105x06xE/F

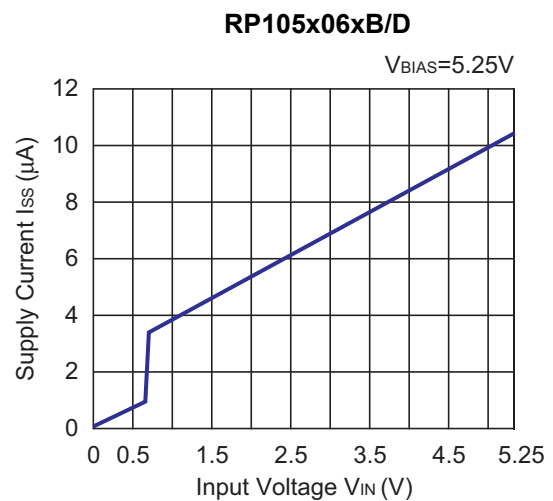
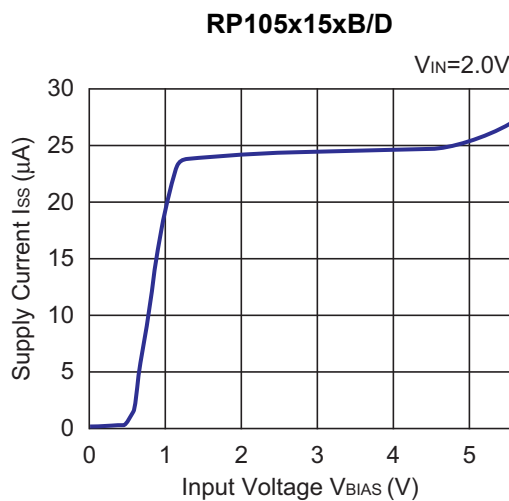
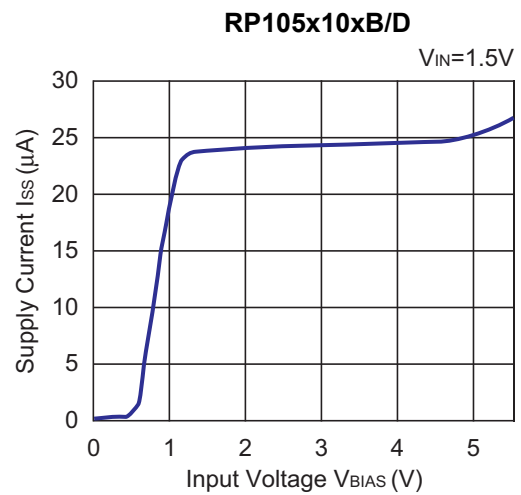
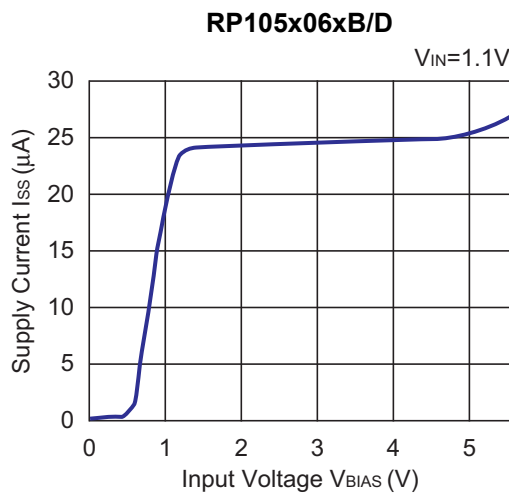


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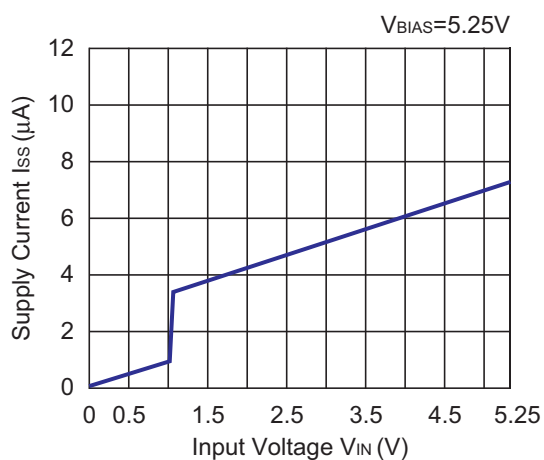


3) Supply Current vs. Input Voltage ($C_{BIAS} = C_{IN} = C_{OUT} = \text{none}$, $T_a = 25^\circ C$)

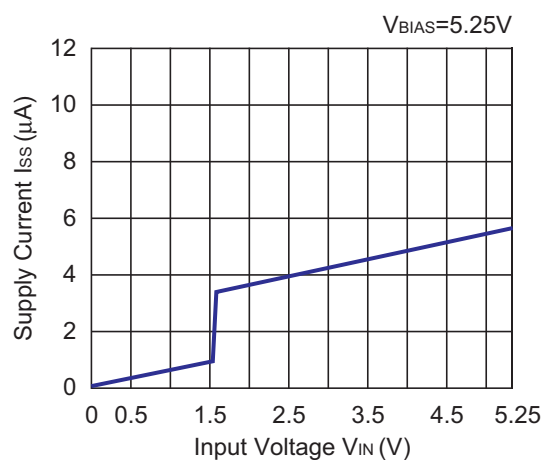


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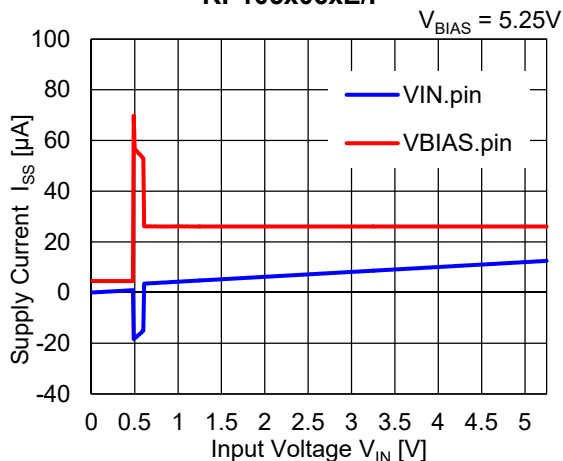
RP105x10xB/D



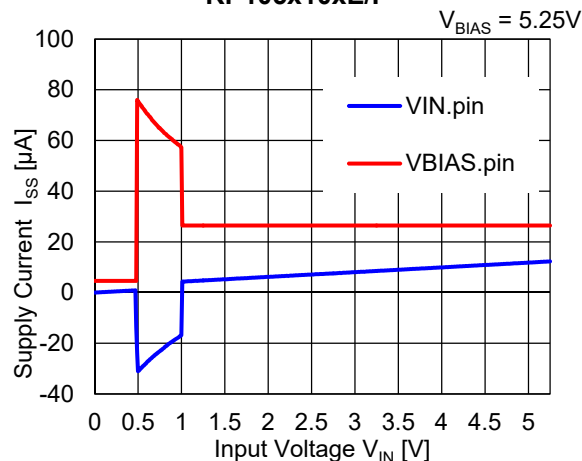
RP105x15xB/D



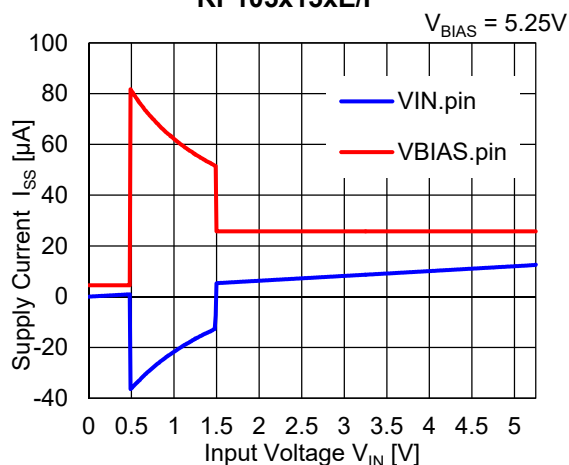
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RP105x10xE/F

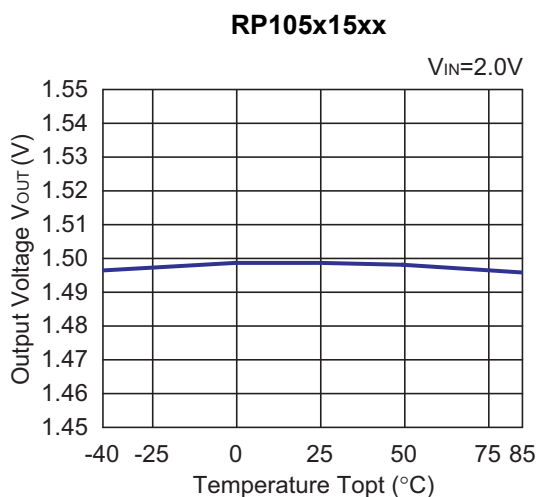
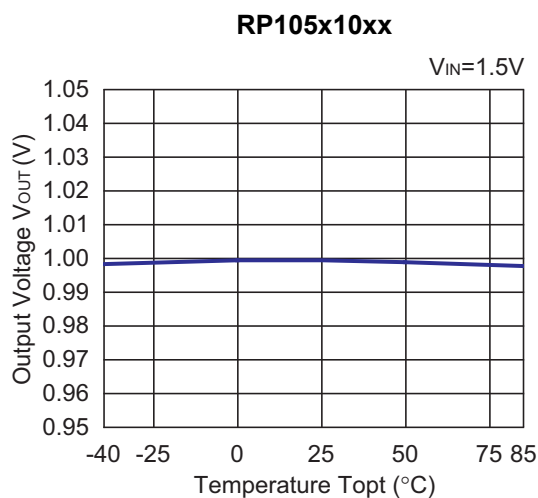
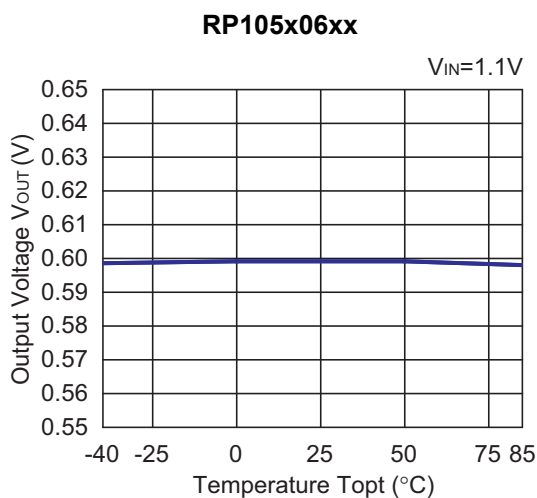


RP105x15xE/F

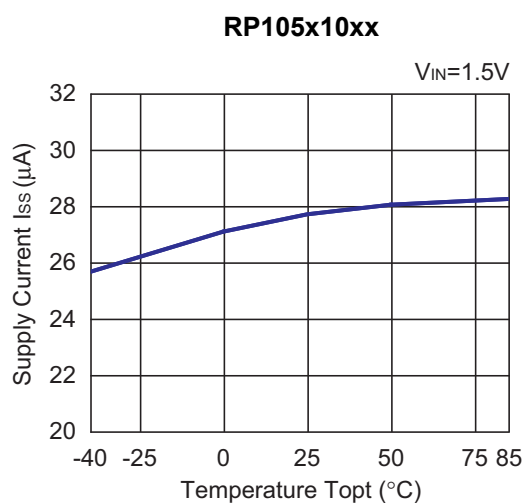
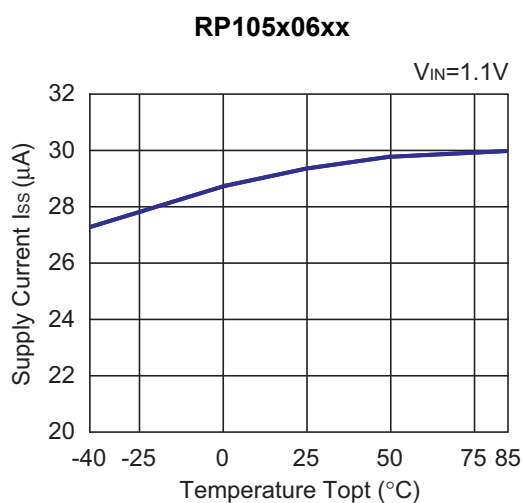


In RP105xxxxE/F, the current flows from V_{BIAS} pin to V_{IN} pin via the inside IC when the input voltage V_{IN} drops below the set output voltage V_{SET} .

4) Output Voltage vs. Temperature ($C_{BIAS} = 1.0 \mu F$, $C_{IN} = C_{OUT} = 2.2 \mu F$, $I_{OUT} = 1 \text{ mA}$, $V_{BIAS} = 3.6 \text{ V}$)

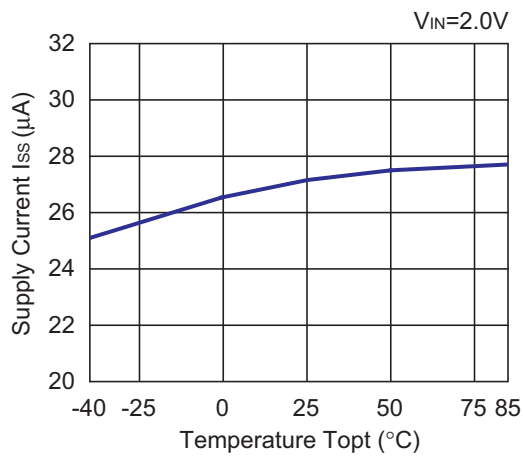


5) Supply Current vs. Temperature ($C_{BIAS} = C_{IN} = C_{OUT} = \text{none}$, $V_{BIAS} = 3.6 \text{ V}$)



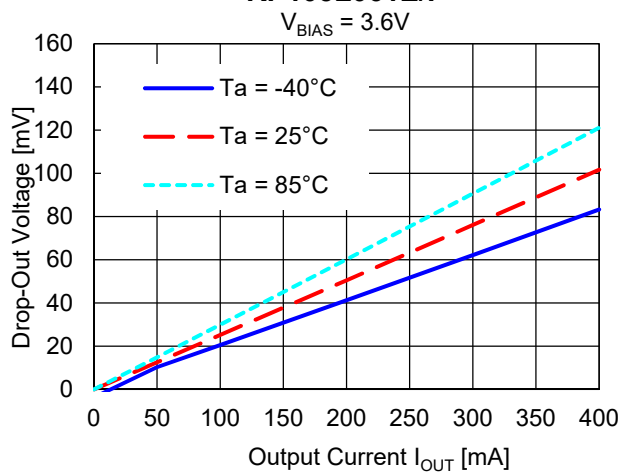
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RP105x15xx

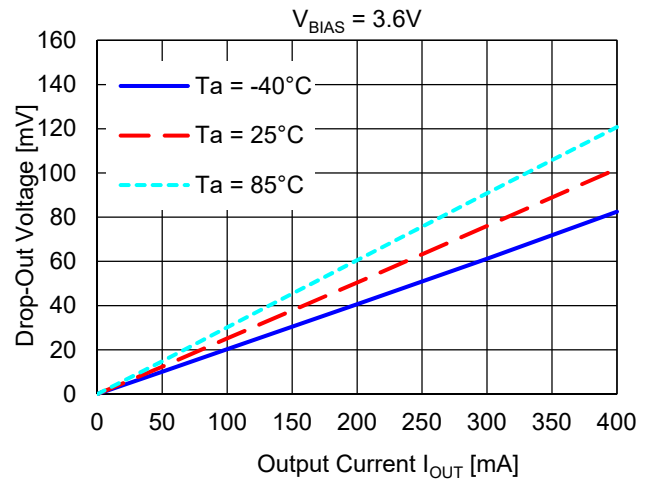


6) Dropout Voltage vs. Output Current ($C_{BIAS} = 1.0 \mu F$, $C_{IN} = C_{OUT} = 2.2 \mu F$)

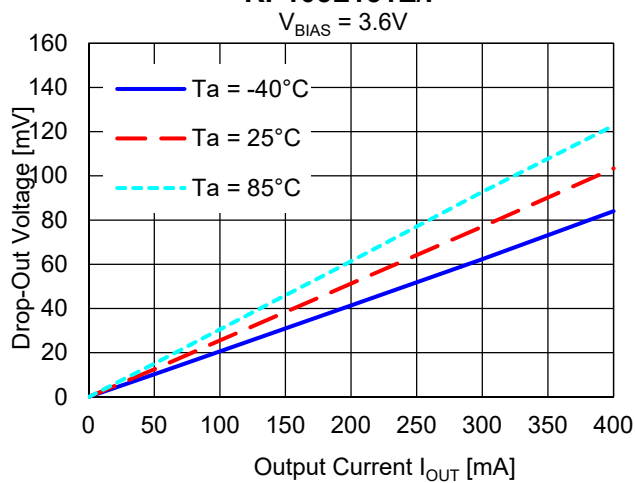
RP105L061E/F



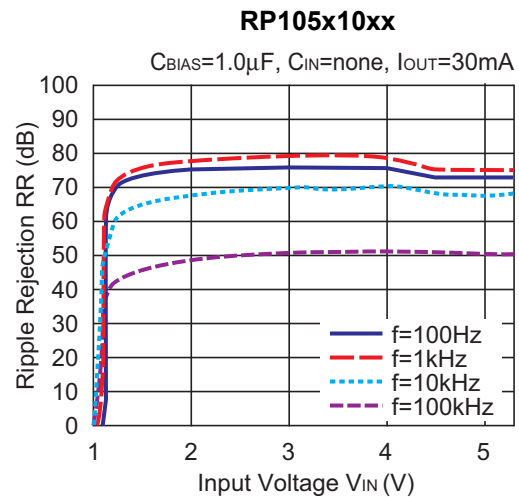
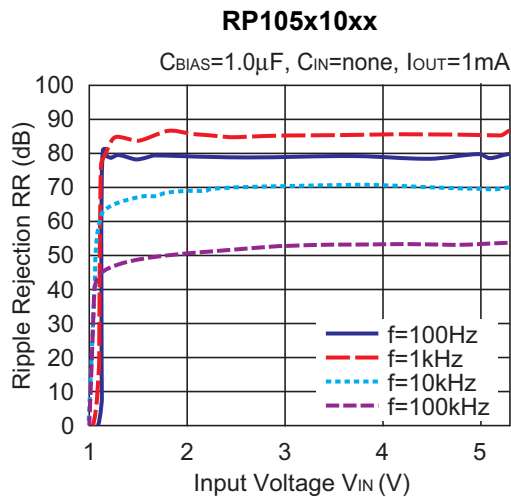
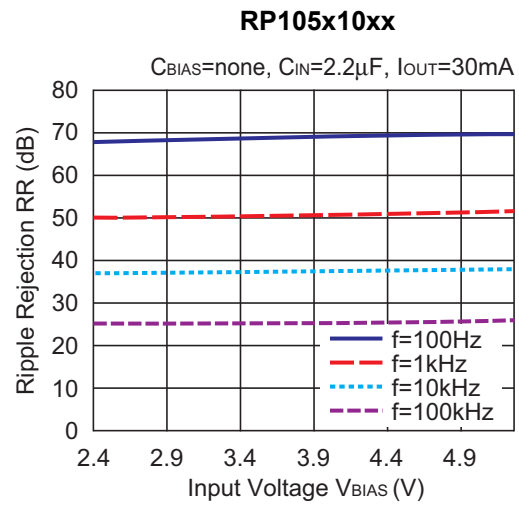
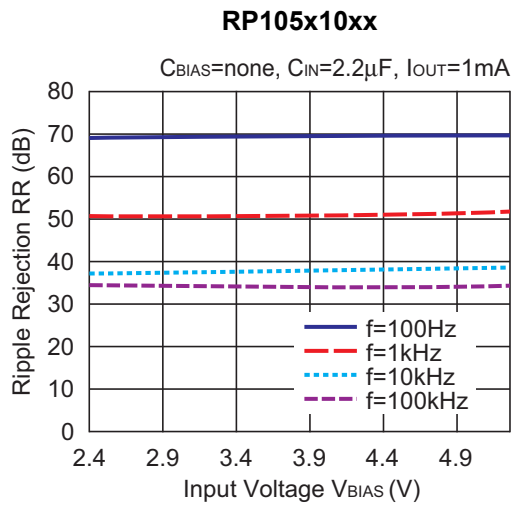
RP105L101E/F



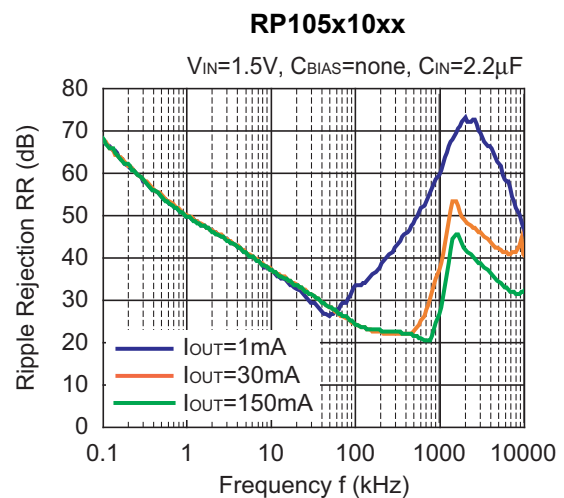
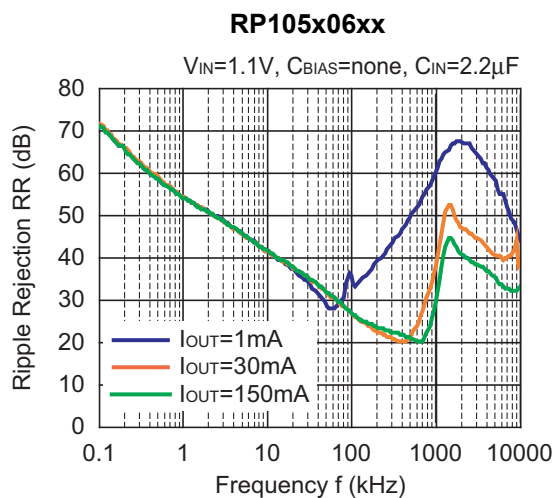
RP105L151E/F



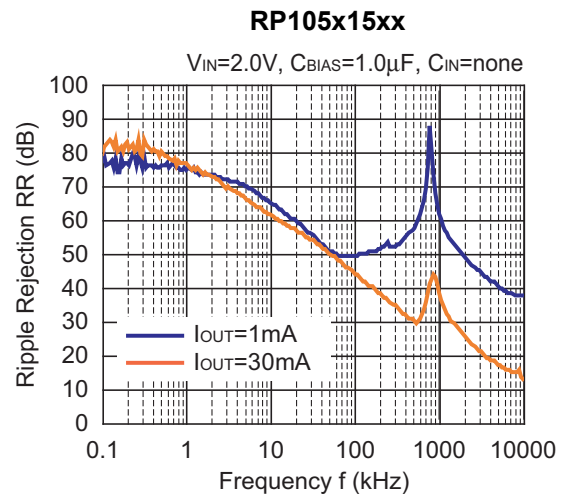
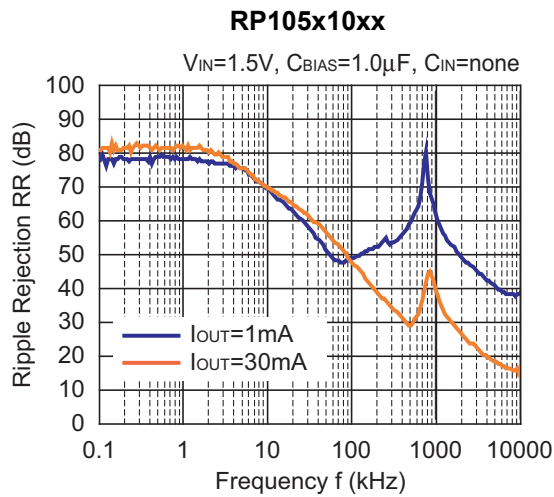
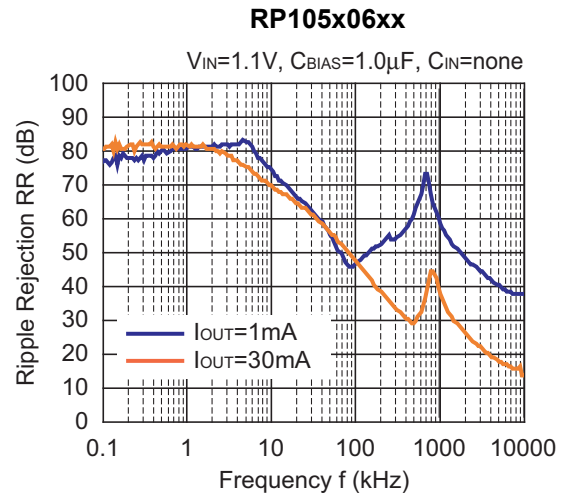
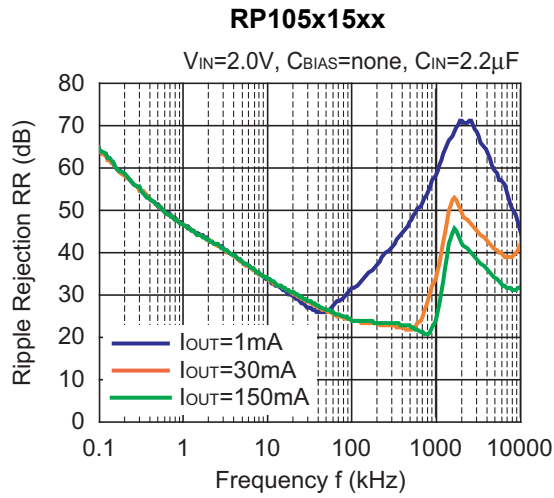
7) Ripple Rejection vs. Input Bias Voltage ($C_{OUT} = 2.2 \mu F$, Ripple = 0.2 Vp-p, $T_a = 25^\circ C$)



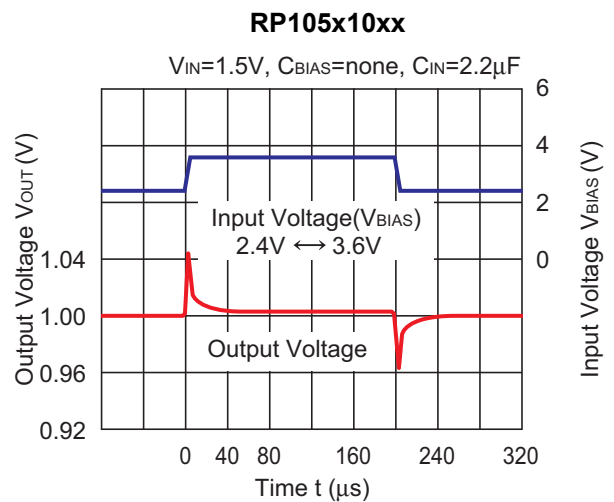
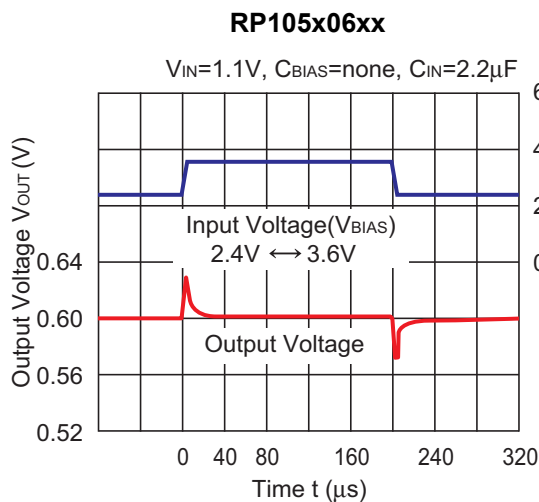
8) Ripple Rejection vs. Frequency ($V_{BIAS} = 3.6 \text{ V}$, $C_{OUT} = 2.2 \mu F$, $T_a = 25^\circ C$)

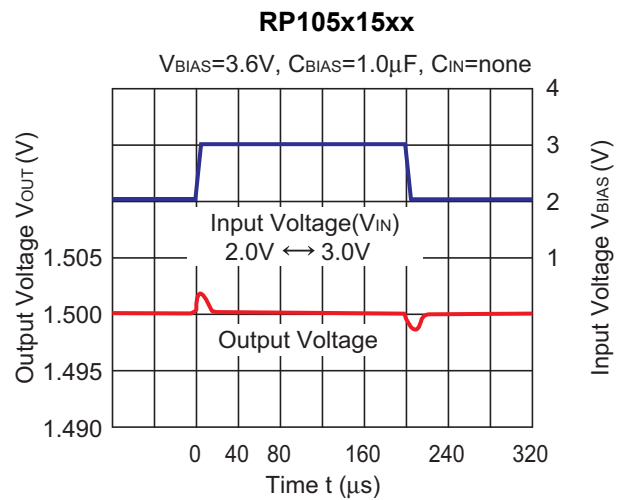
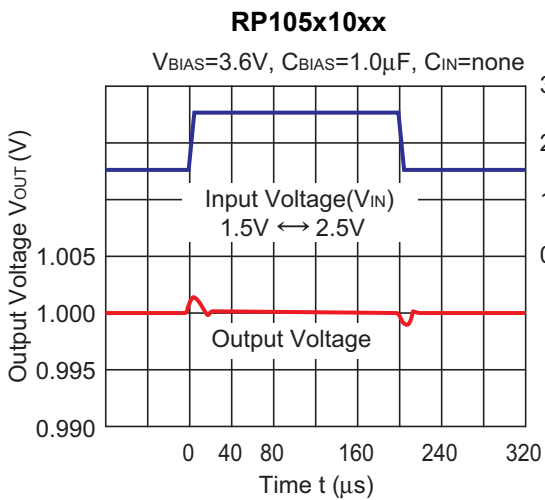
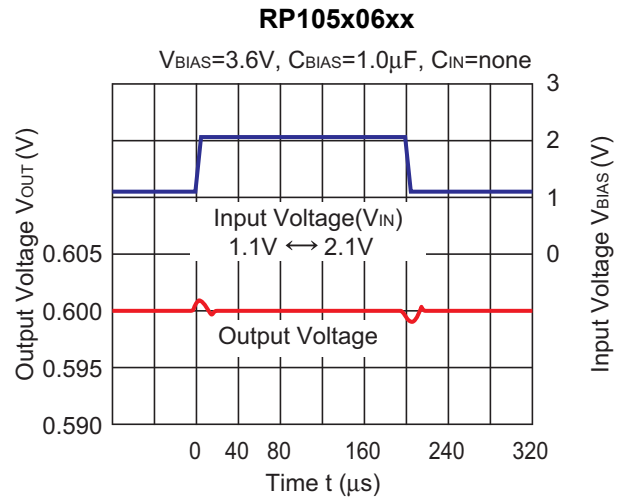
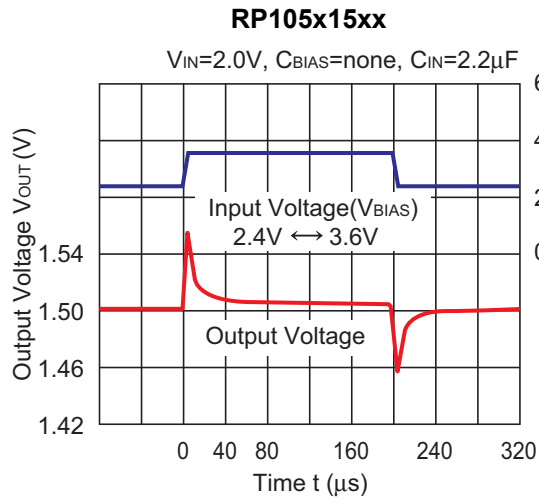


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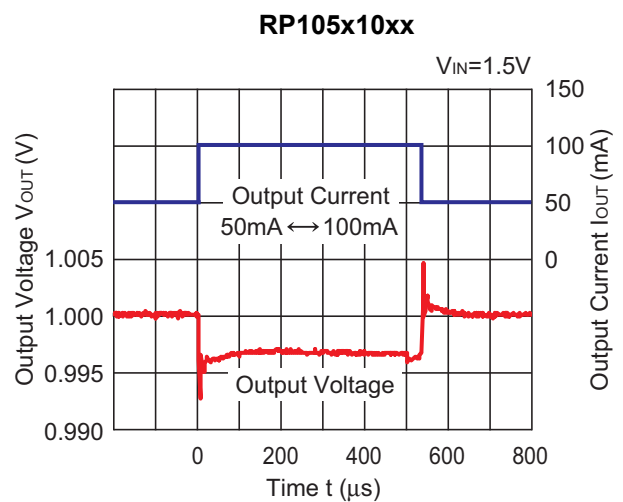
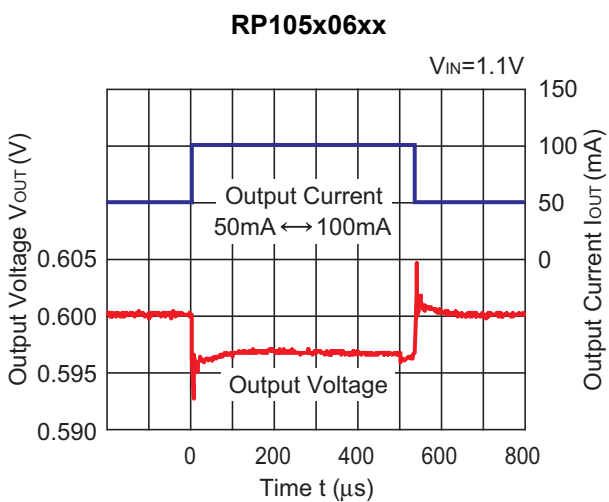


9) Input Transient Response ($I_{OUT} = 30\text{ mA}$, $C_{OUT} = 1.0\mu F$, $t_r = t_f = 5\mu s$, $T_a = 25^\circ C$)

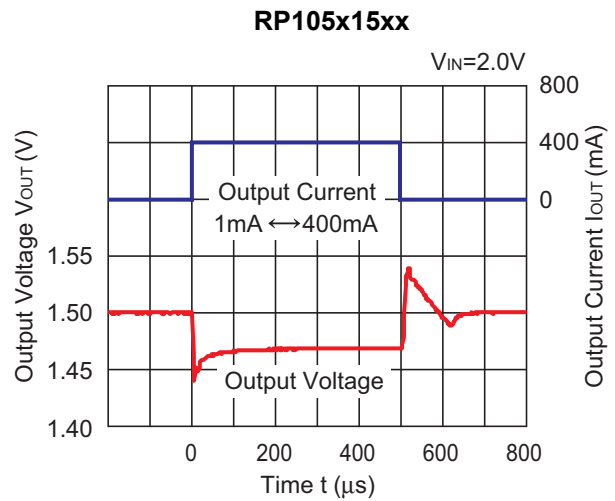
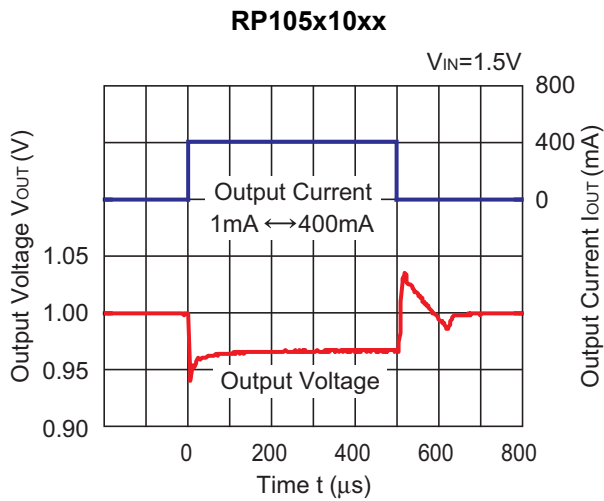
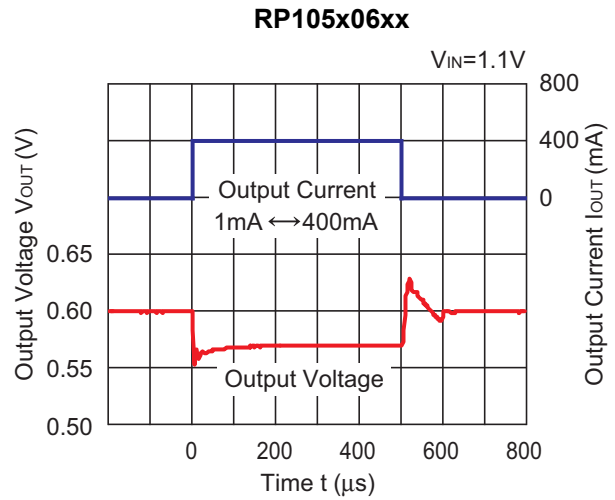
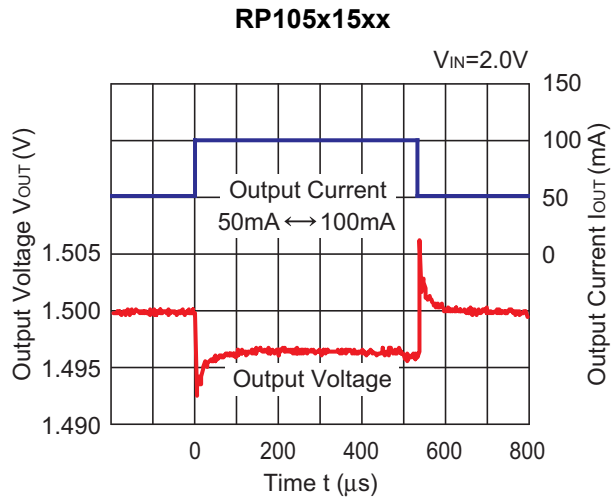




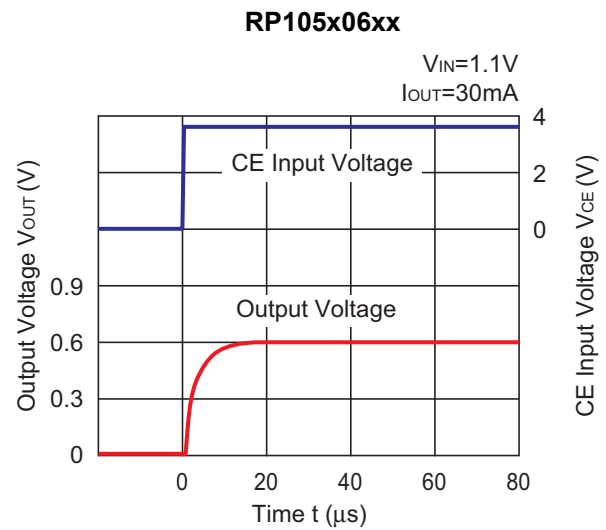
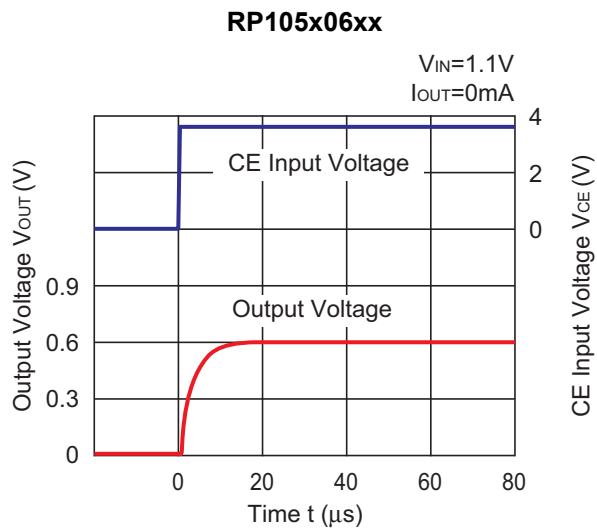
10) Load Transient Response ($V_{BIAS} = 3.6V$, $C_{BIAS} = 1.0\mu F$, $C_{IN} = C_{OUT} = 2.2\mu F$, $t_r = t_f = 0.5\mu s$, $T_a = 25^\circ C$)



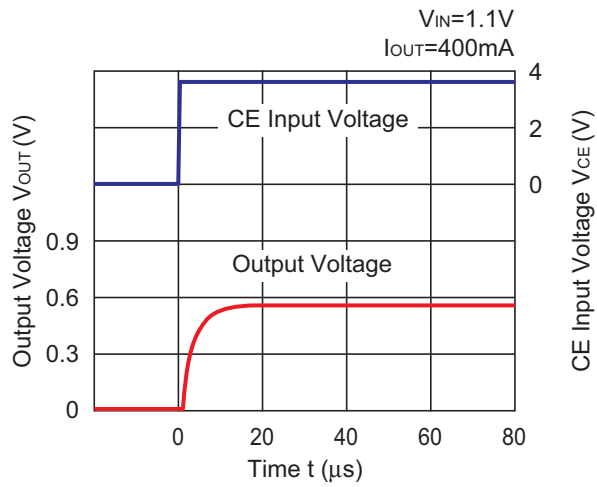
No. EA-179-180419



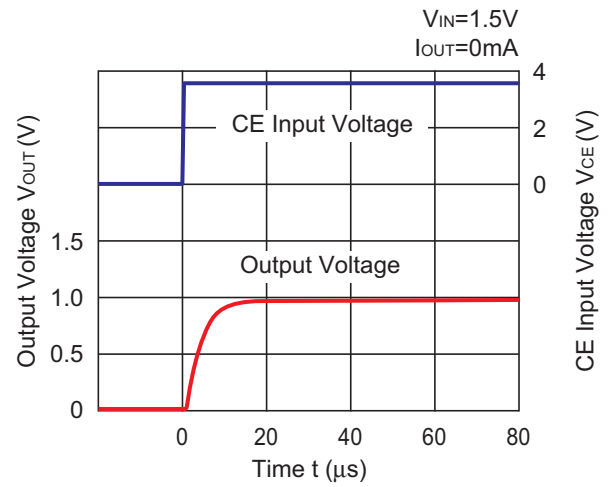
11) Turn On Speed with CE pin ($V_{BIAS} = 3.6V$, $C_{BIAS} = 1.0\mu F$, $C_{IN} = C_{OUT} = 2.2\mu F$, $T_a = 25^\circ C$)



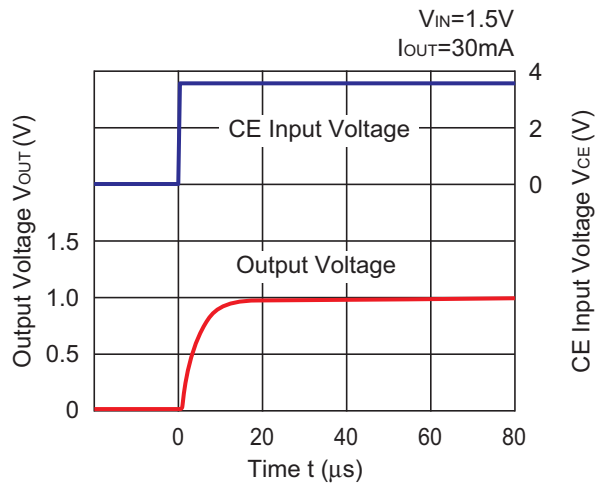
RP105x06xx



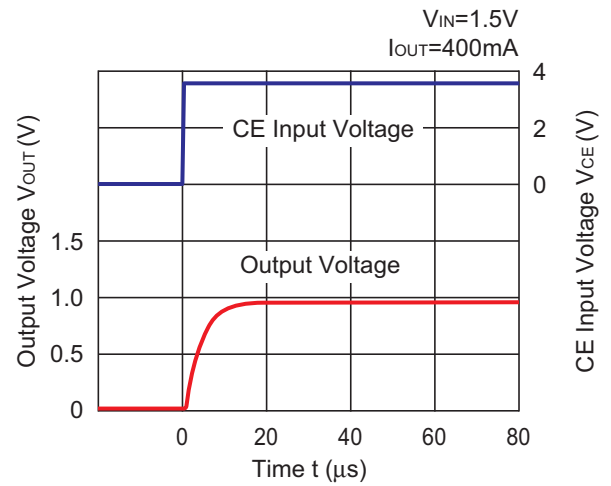
RP105x10xx



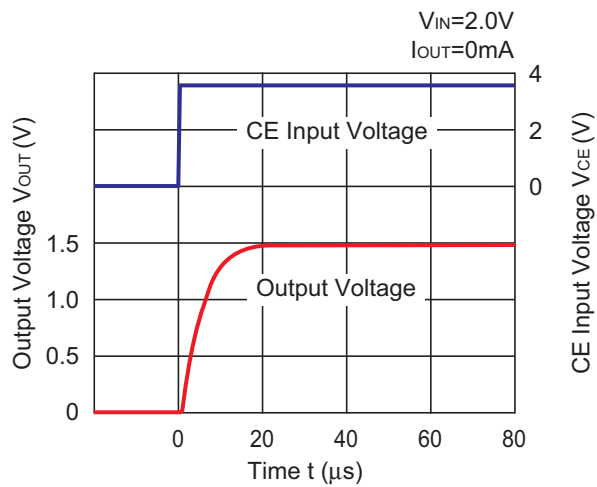
RP105x10xx



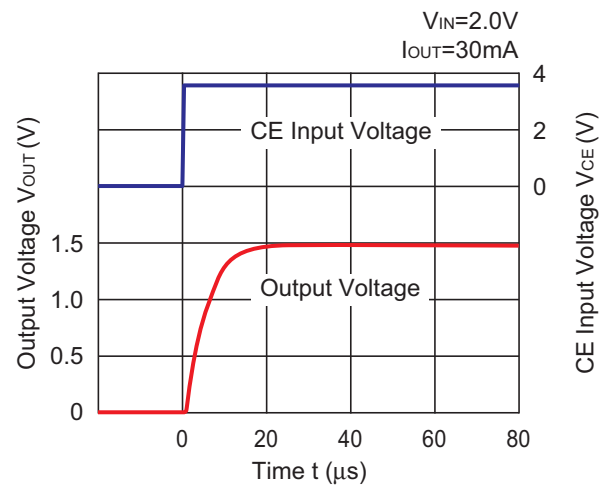
RP105x10xx



RP105x15xx

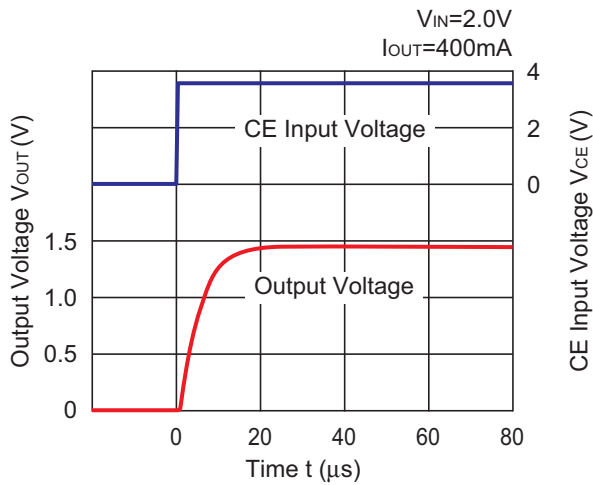


RP105x15xx



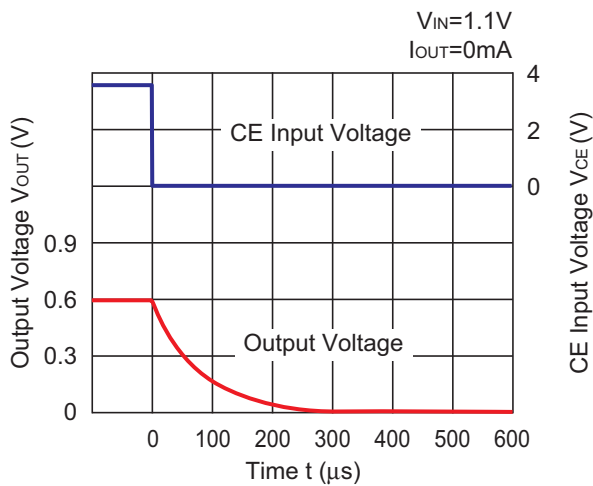
No. EA-179-180419

RP105x15xx

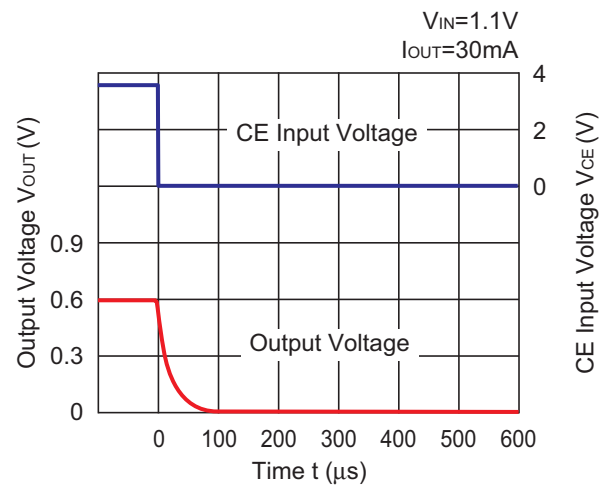


12) Turn Off Speed with CE Pin ($V_{BIAS} = 3.6V$, $C_{BIAS} = 1.0\mu F$, $C_{IN} = C_{OUT} = 2.2\mu F$, $T_a = 25^\circ C$)

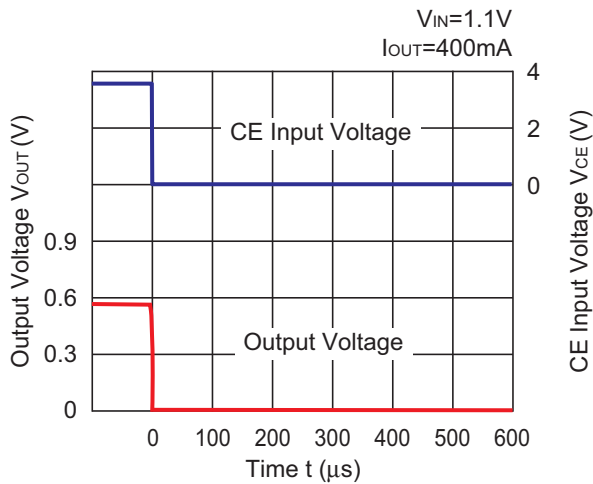
RP105x06xD/F



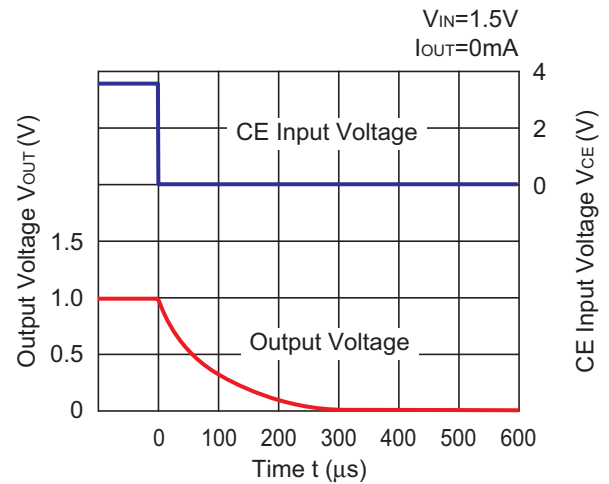
RP105x06xD/F



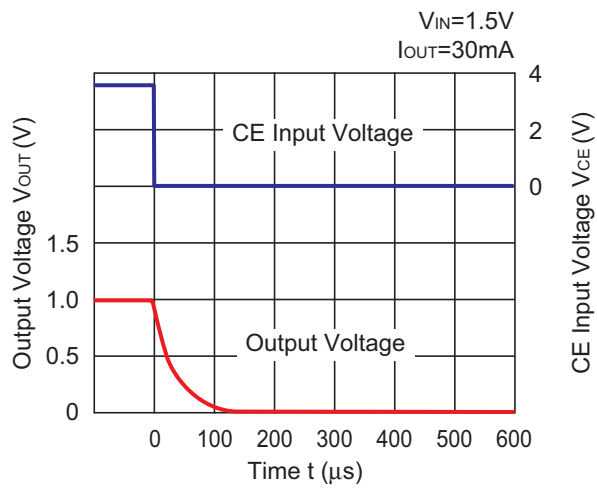
RP105x06xD/F



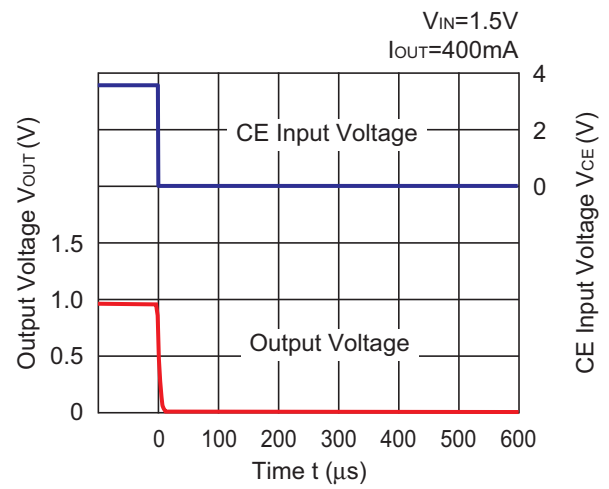
RP105x10xD/F



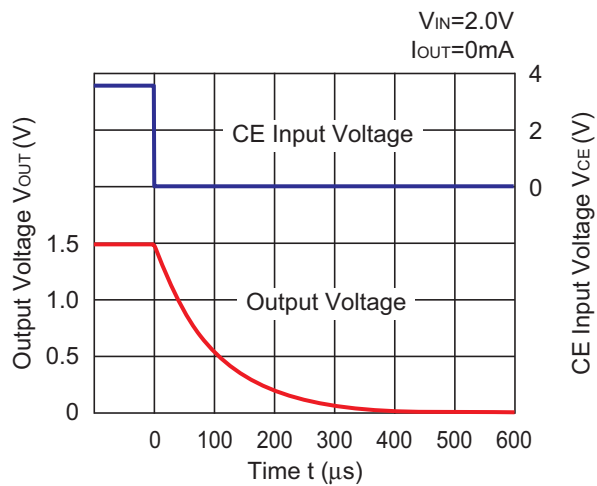
RP105x10xD/F



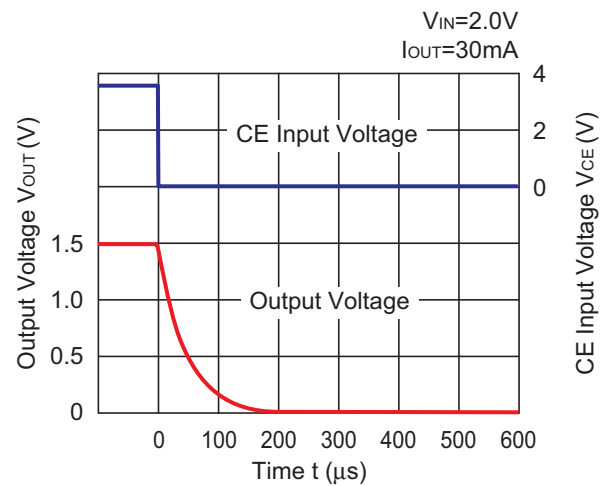
RP105x10xD/F



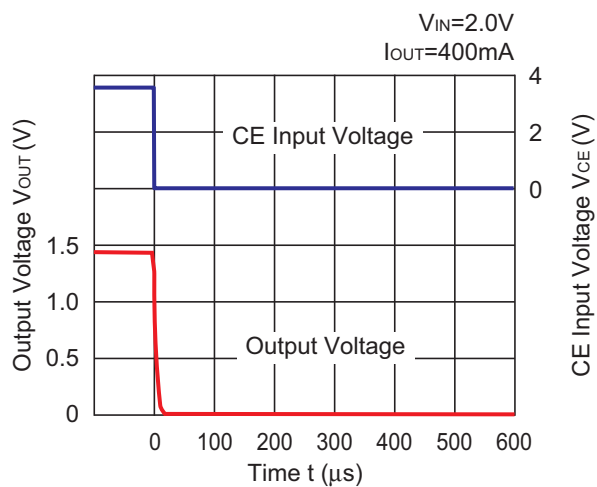
RP105x15xD/F



RP105x15xD/F

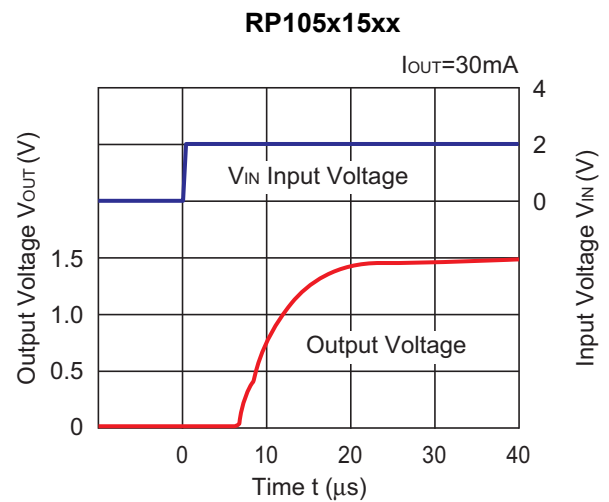
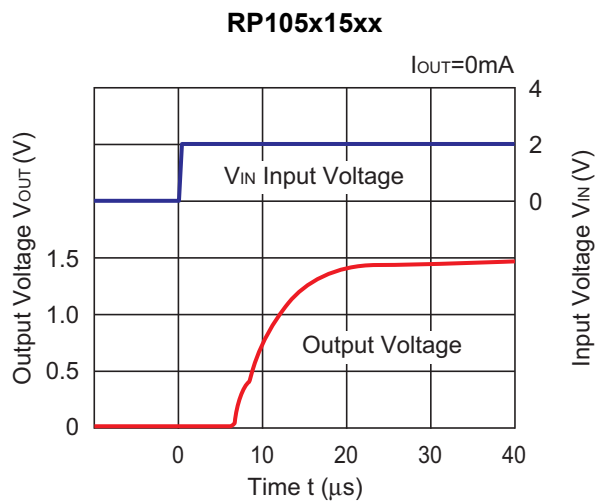
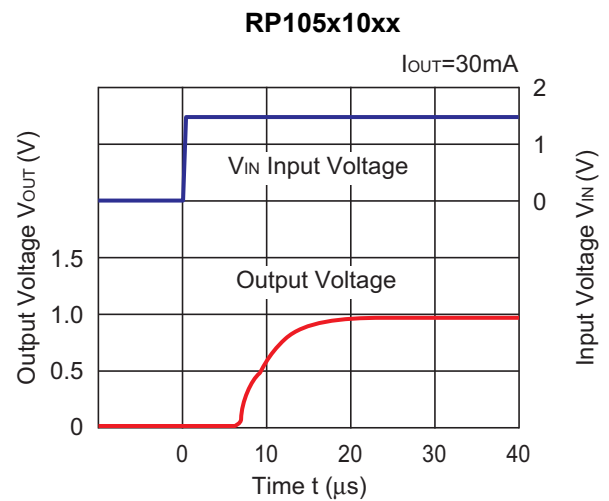
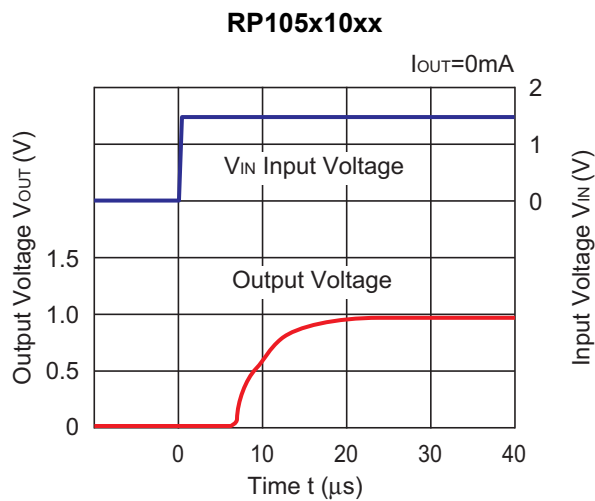
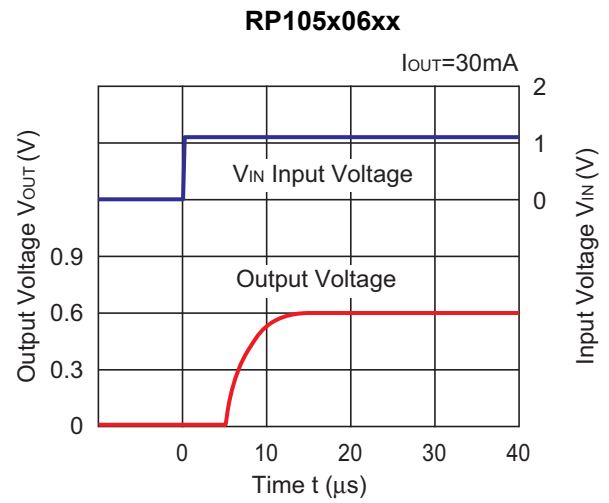
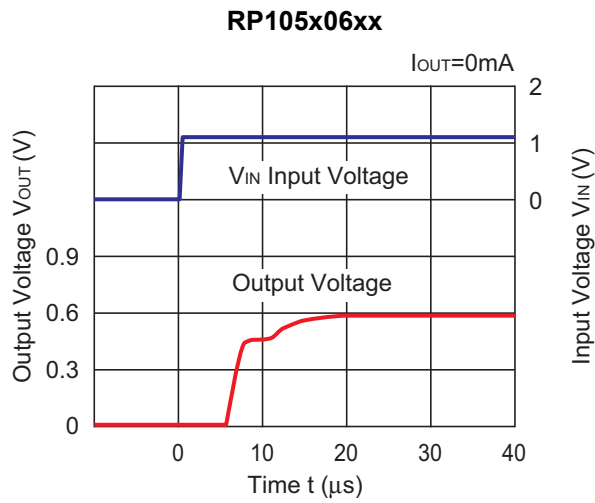


RP105x15xD/F



No. EA-179-180419

13) Turn On Transient with V_{IN} pin ($V_{BIAS} = 3.6\text{ V}$, $C_{BIAS} = 1.0\text{ }\mu\text{F}$, $C_{IN} = \text{none}$, $C_{OUT} = 2.2\text{ }\mu\text{F}$, $T_a = 25^\circ\text{C}$)



ESR vs. Output Current

Ceramic type output capacitor is recommended for this series; however, the other output capacitors with low ESR also can be used. The relations between I_{OUT} (Output Current) and ESR of an output capacitor are shown below. The conditions when the white noise level is under 40 μV (Avg.) are marked as the hatched area in the graph.

Measurement conditions

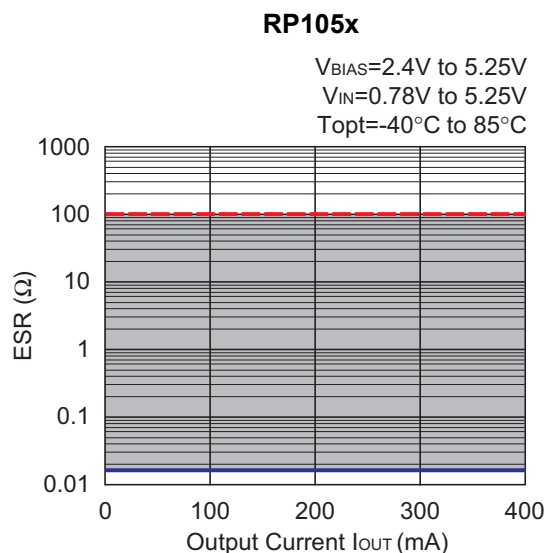
Frequency Band: 10 Hz to 2 MHz

Temperature : $-40^{\circ}C$ to $85^{\circ}C$

Hatched Area : Noise level is under 40 μV (Avg.)

C_{BIAS} , C_{IN} : 1.0 μF

C_{OUT} : 2.2 μF



The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

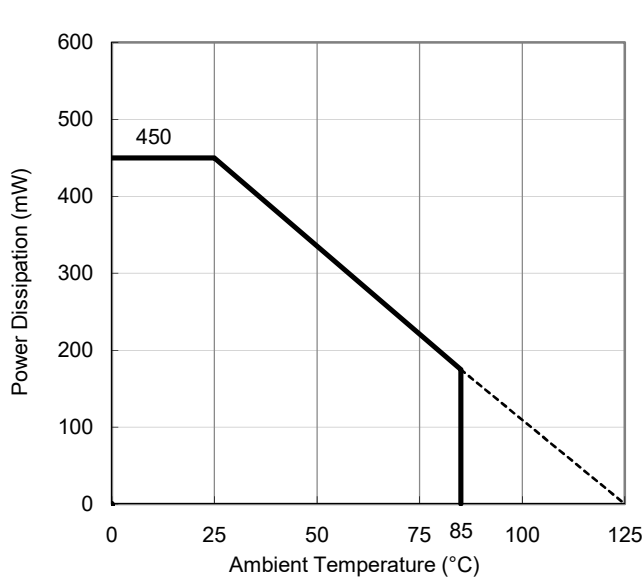
Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.2 mm × 14 pcs

Measurement Result

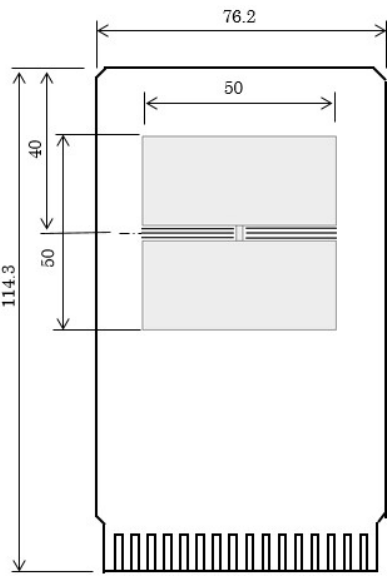
(Ta = 25°C, TJmax = 125°C)

Item	Measurement Result
Power Dissipation	450 mW
Thermal Resistance (θja)	θja = 218°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 105°C/W

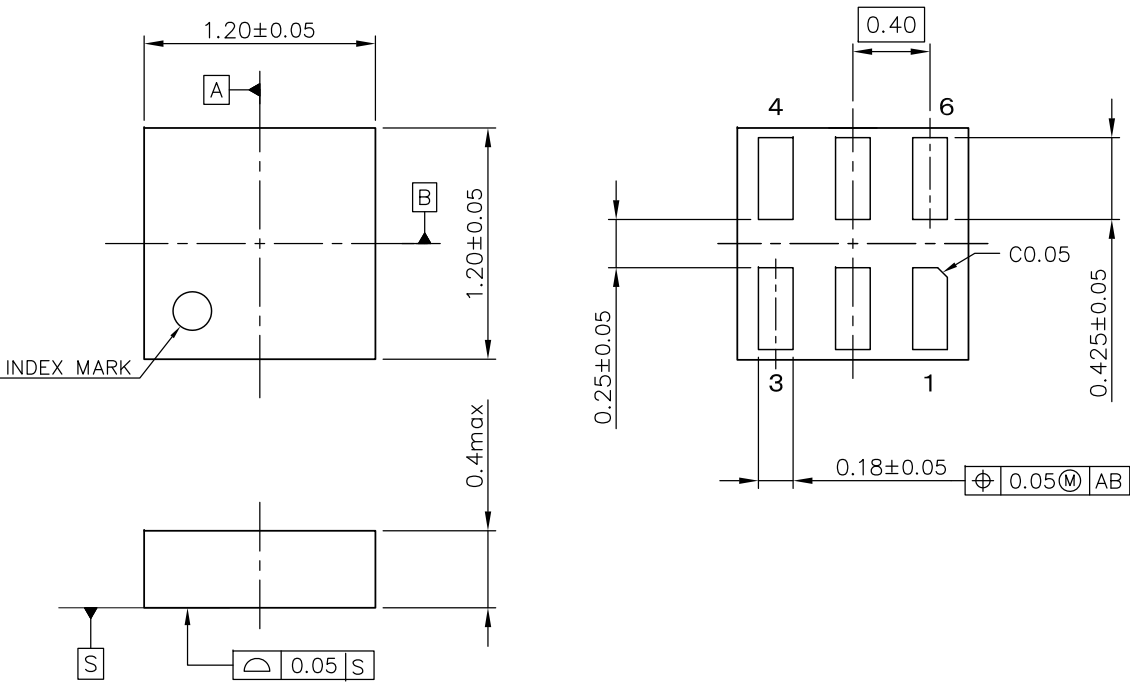
θja: Junction-to-Ambient Thermal Resistance
ψjt: Junction-to-Top Thermal Characterization Parameter



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern



UNIT: mm

DFN(PLP)1212-6 Package Dimensions

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

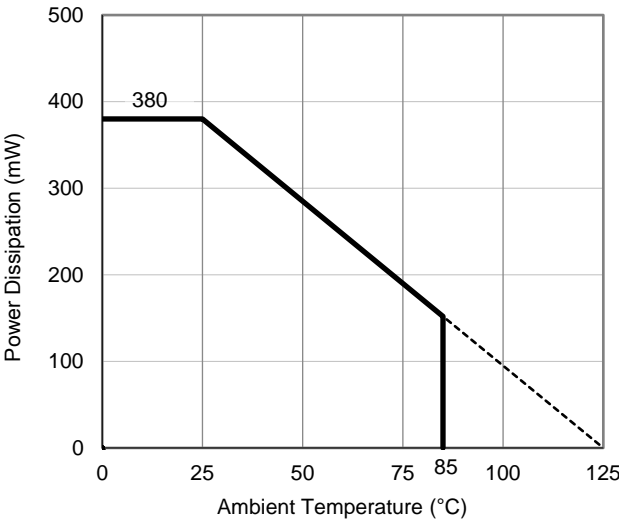
Measurement Conditions

Item	Standard Test Land Pattern
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Double-Sided Board)
Board Dimensions	40 mm × 40 mm × 1.6 mm
Copper Ratio	Top Side: Approx. 50% Bottom Side: Approx. 50%
Through-holes	φ 0.5 mm × 44 pcs

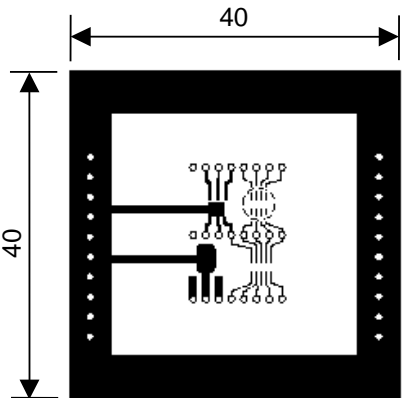
Measurement Result (Ta = 25°C, Tjmax = 125°C)

Item	Standard Test Land Pattern
Power Dissipation	380 mW
Thermal Resistance (θja)	θja = 263°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 75°C/W

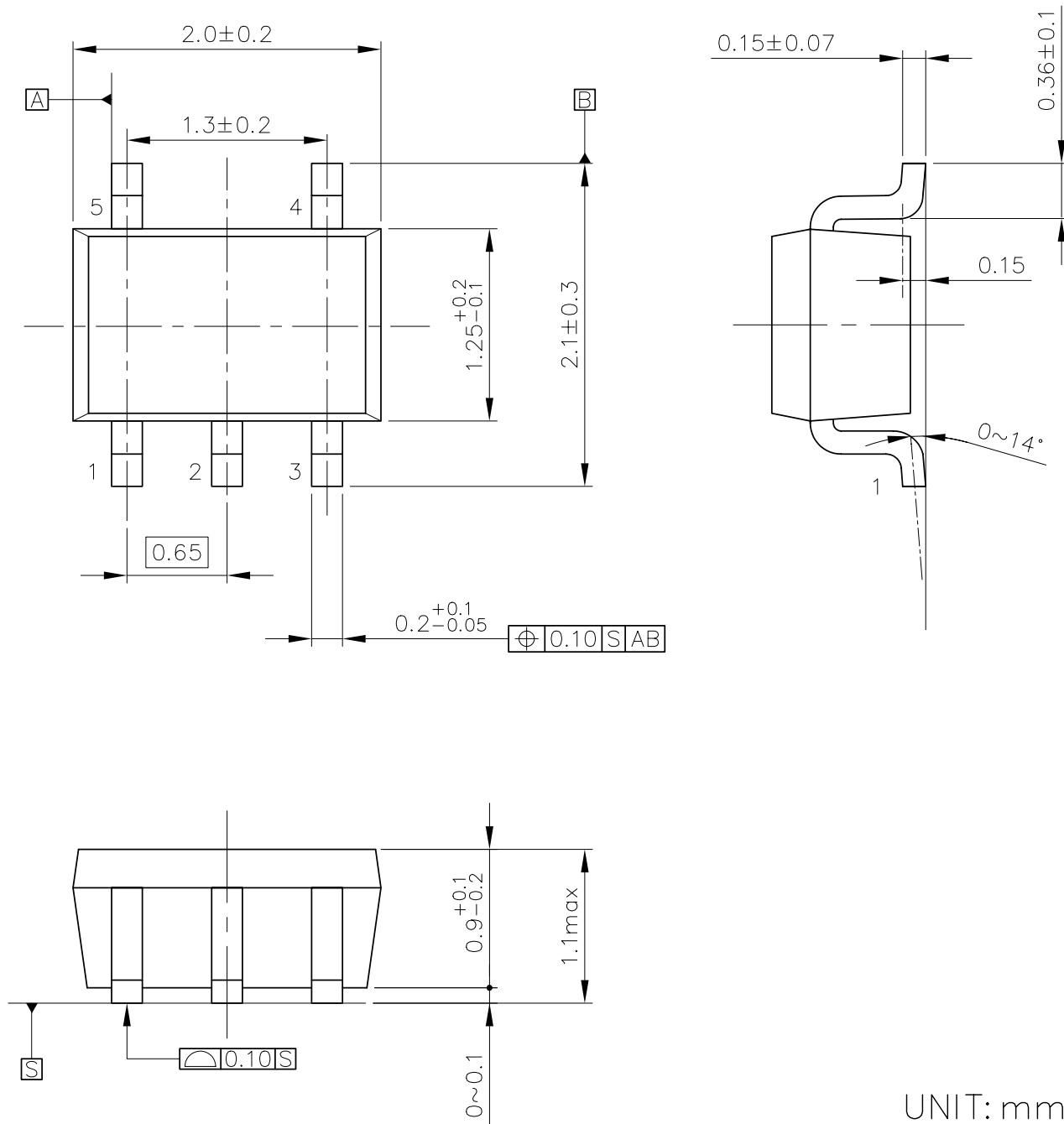
θja: Junction-to-Ambient Thermal Resistance
ψjt: Junction-to-Top Thermal Characterization Parameter



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern



SC-88A Package Dimensions

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

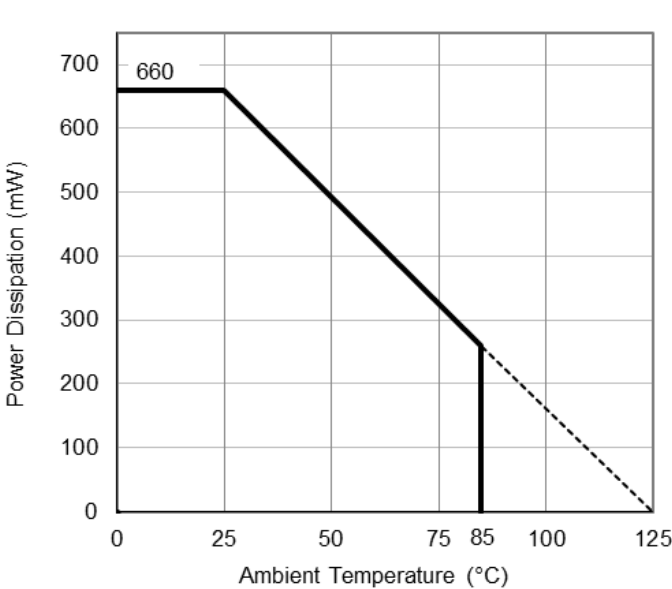
Measurement Conditions

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 7 pcs

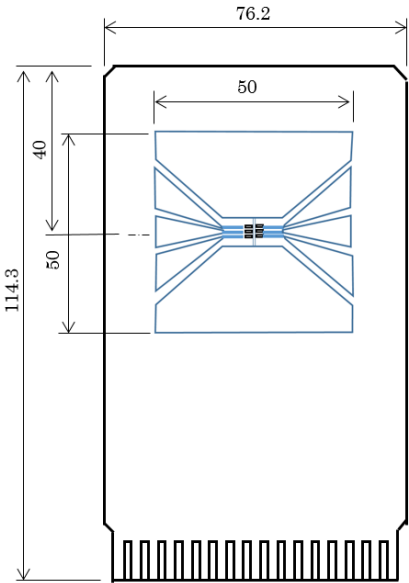
Measurement Result (Ta = 25°C, Tjmax = 125°C)

Item	Measurement Result
Power Dissipation	660 mW
Thermal Resistance (θja)	θja = 150°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 51°C/W

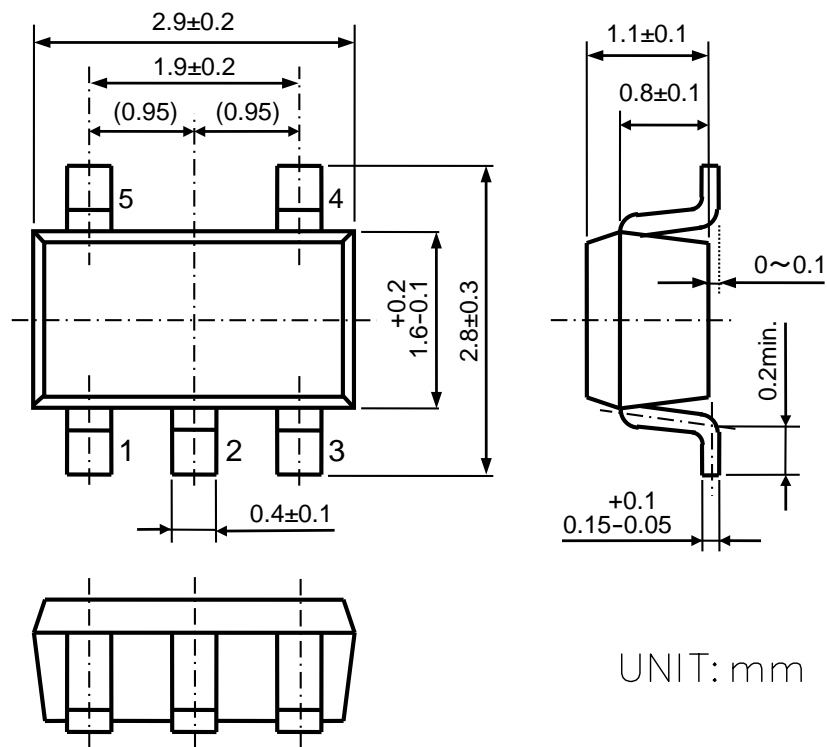
θja: Junction-to-Ambient Thermal Resistance
ψjt: Junction-to-Top Thermal Characterization Parameter



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern



SOT-23-5 Package Dimensions

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

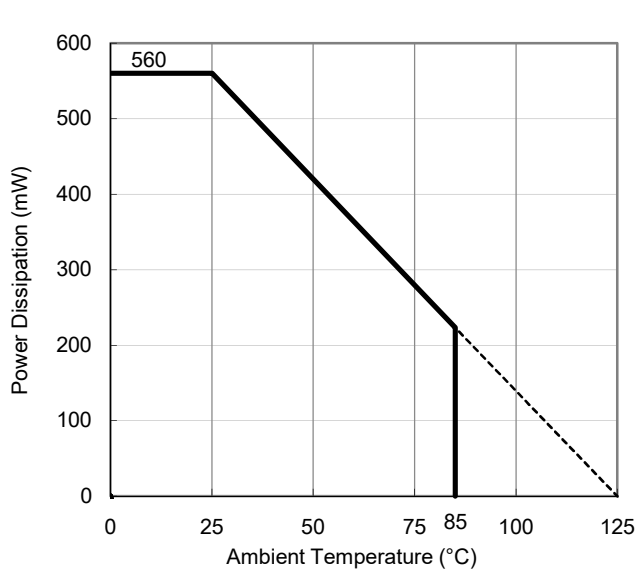
Measurement Conditions

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.2 mm × 14 pcs

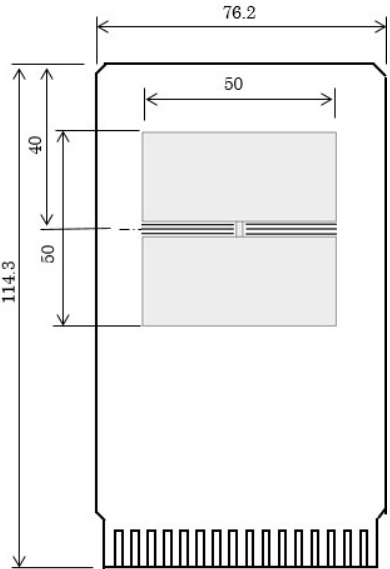
Measurement Result (Ta = 25°C, Tjmax = 125°C)

Item	Measurement Result
Power Dissipation	560 mW
Thermal Resistance (θja)	θja = 178°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 105°C/W

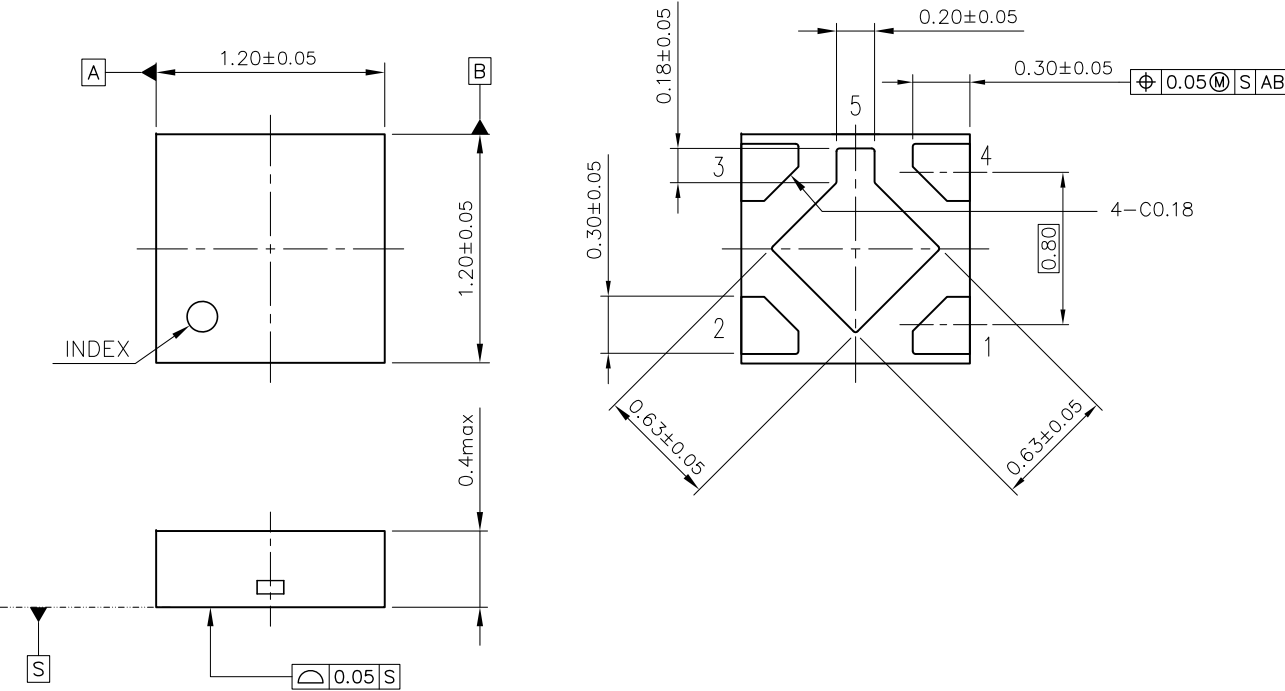
θja: Junction-to-Ambient Thermal Resistance
ψjt: Junction-to-Top Thermal Characterization Parameter



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern



DFN1212-5 Package Dimensions (Unit: mm)